

Type 1XA Wi-Fi® + Bluetooth® Module

Infineon Chipset CYW54591 for 802.11a/b/g/n/ac 2x2 MIMO, RSDB + Bluetooth 5.2 Datasheet - Rev. L

- Design Name: Type 1XA
- Module P/N: LBEE5XV1XA-540



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About This Document

Type 1XA is a small and very high-performance module based on Infineon CYW54591 combo chipset which supports Wi-Fi 802.11a/b/g/n/ac 2x2 MIMO RSDB + Bluetooth 5.2 BR/EDR/LE. This datasheet describes Type 1XA module in detail.



Please be aware that an important notice concerning availability, standard warranty and use in critical applications of Murata products and disclaimers thereto appears at the end of this specification sheet.









Audience & Purpose

Intended audience includes any customer looking to integrate this module into their product; specifically RF, hardware, software, and systems engineers.

Document Conventions

Table 1 describes the document conventions.


Table 1: Document Conventions

Conventions	Description
	Warning Note Indicates very important note. Users are strongly recommended to review.
	Info Note Intended for informational purposes. Users should review.
	Menu Reference Indicates menu navigation instructions. Example: Insert → Tables → Quick Tables → Save Selection to Gallery 
	External Hyperlink This symbol indicates a hyperlink to an external document or website. Example: Murata  Click on the text to open the external link.
	Internal Hyperlink This symbol indicates a hyperlink within the document. Example: Scope  Click on the text to open the link.
<code>Console input/output or code snippet</code>	Console I/O or Code Snippet This text Style denotes console input/output or a code snippet.
<code># Console I/O comment // Code snippet comment</code>	Console I/O or Code Snippet Comment This text Style denotes a console input/output or code snippet comment. <ul style="list-style-type: none"> • Console I/O comment (preceded by "#") is for informational purposes only and does not denote actual console input/output. • Code Snippet comment (preceded by "//") may exist in the original code.

1 Scope

This specification characterizes the IEEE 802.11a/b/g/n/ac 2x2 MIMO + Bluetooth 5.2 BR/EDR/LE combo module.

2 Key Features

- ◆ Infineon CYW54591 inside
- ◆ Supports IEEE 802.11a/b/g/n/ac specification: Dual band 2.4 GHz and 5 GHz
- ◆ 2x2 MIMO with 20 MHz, 40 MHz, and 80 MHz channels
- ◆ Supports RSDB (Real Simultaneous Dual Band)
- ◆ Up to MCS9 data rates (866 Mbps)
- ◆ Supports Bluetooth specification version 5.2
- ◆ For supported Bluetooth functions, refer to [Bluetooth SIG site](#) 
- ◆ WLAN interface: PCIe 3.0
- ◆ Bluetooth interface: HCI UART and PCM
- ◆ Temperature Range: -40 °C to 85 °C
- ◆ Dimensions 11.4 x 8.9 x 1.4 mm
- ◆ Weight: 0.36 g
- ◆ MSL: 3
- ◆ Surface-mount type
- ◆ RoHS compliant

3 Ordering Information

Table 2 shows the ordering information.

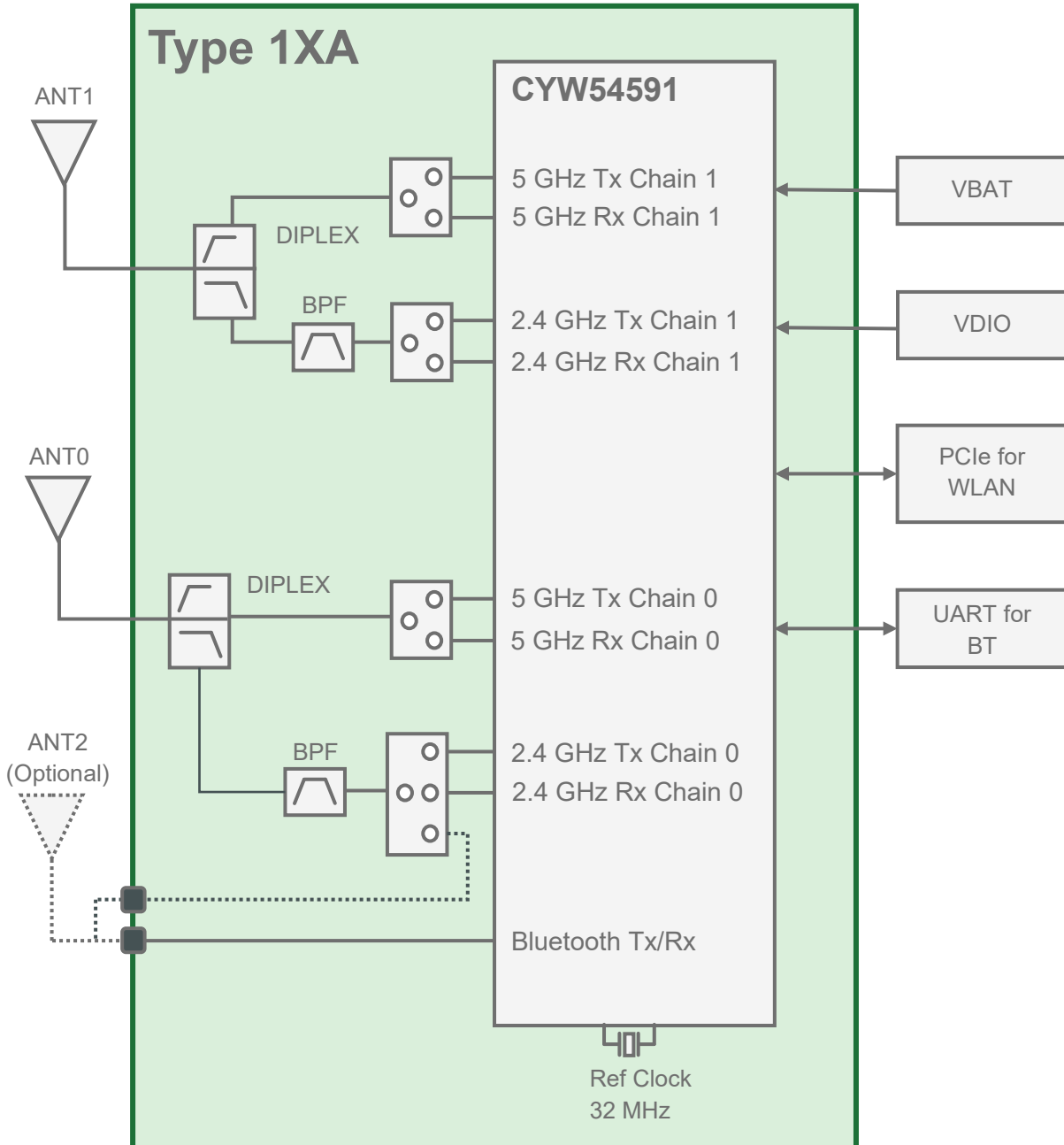
Table 2: Ordering Information

Ordering Part Number	Description
LBEE5XV1XA-540	Module order
LBEE5XV1XA-SMP	Sample module order (If module samples are not available through distribution, contact Murata referencing this part number)
EAR00373	Embedded Artists Type 1XA M.2 EVB (default EVB available through distribution)
LBEE5XV1XA-EVB	Murata Type 1XA M.2 EVB (contact Murata as this is special order item)

4 Block Diagram

The Type 1XA block diagram is presented in **Figure 1**.

Figure 1: Block Diagram



5 Dimensions, Markings and Terminal Configurations

This section has information on dimensions, markings, and terminal configurations for Type 1XA.

Figure 2: Dimensions, Markings and Terminal Configurations

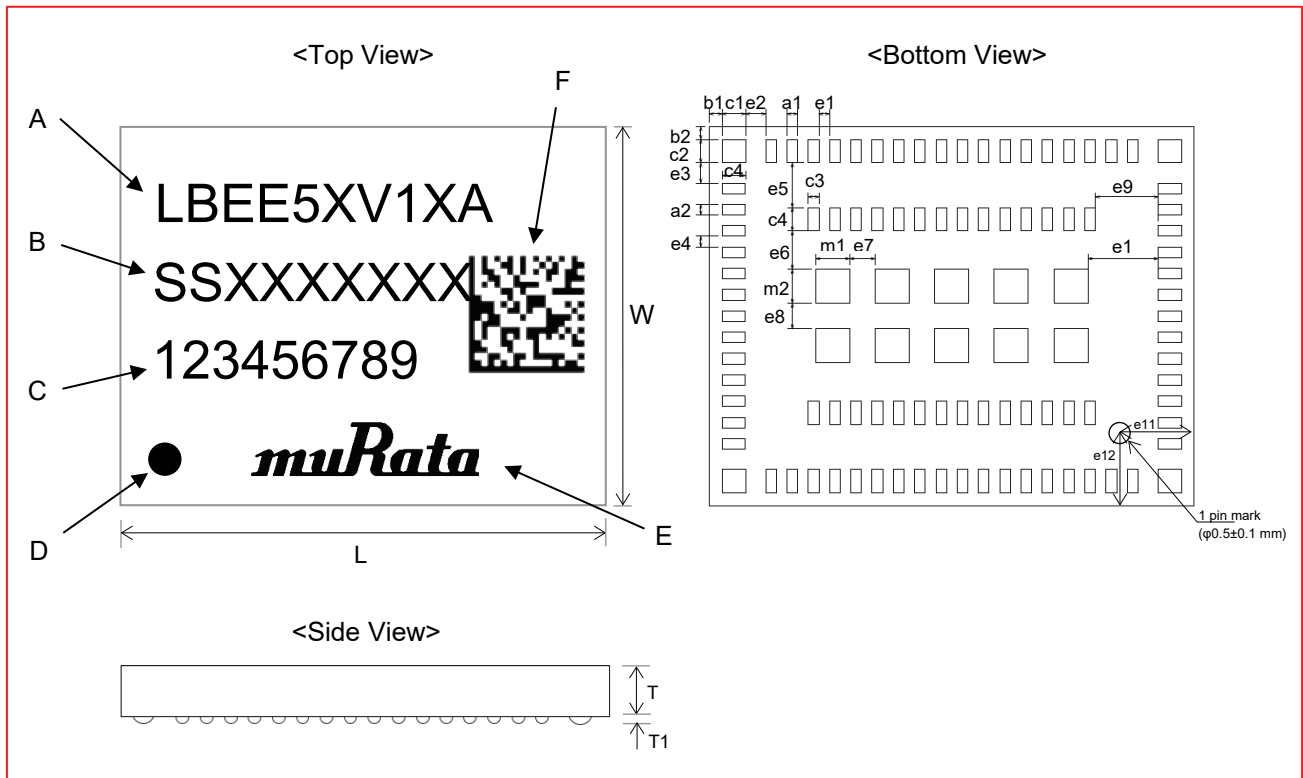


Table 3 describes the marking labels for the top and bottom view as shown in **Figure 2**.

Table 3: Markings

Marking	Meaning
A	Module Part Number
B	Inspection Number
C	Serial Number
D	Pin 1 Marking
E	Murata Logo
F	2D code

Table 4 describes the Type 1XA dimensions.

Table 4: Dimensions

Mark	Dimensions (mm)	Mark	Dimensions (mm)	Mark	Dimensions (mm)	Mark	Dimensions (mm)
L	11.4 ± 0.2	W	8.9 ± 0.2	T	1.4 max.	T1	0.04 typ.
a1	0.25 ± 0.1	a2	0.25 ± 0.1	b1	0.3 ± 0.2	b2	0.3 ± 0.2
c1	0.55 ± 0.1	c2	0.55 ± 0.1	c3	0.25 ± 0.1	c4	0.55 ± 0.1
e1	0.25 ± 0.1	e2	0.475 ± 0.1	e3	0.475 ± 0.1	e4	0.25 ± 0.1
e5	1.05 ± 0.1	e6	0.9 ± 0.1	e7	0.6 ± 0.1	e8	0.6 ± 0.1
e9	1.475 ± 0.1	e10	1.65 ± 0.1	e11	1.787 ± 0.2	e12	1.609 ± 0.2
m1	0.8 ± 0.1	m2	0.8 ± 0.1				

6 Module Pin Descriptions

This section describes the module pin assignments layout descriptions along with the pin descriptions.

6.1 Pin Assignments

The pin assignment (top view) layout is shown in **Figure 3**.

Figure 3: Pin Assignments (Top View)

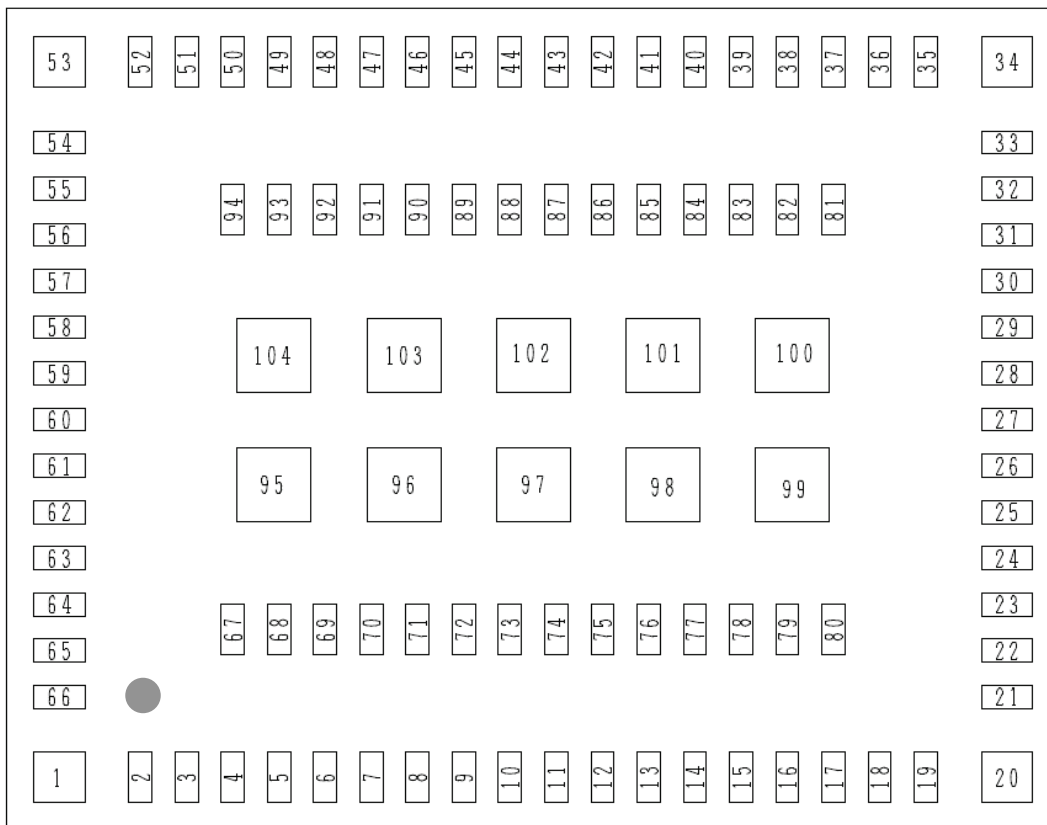


Table 5 illustrates the terminal configurations for Type 1XA.

Table 5: Terminal Configurations

No.	Terminal Name	No.	Terminal Name	No.	Terminal Name
1	GND	31	RF_SW_CTRL11	61	NC
2	GPIO_17	32	GND	62	NC
3	GPIO_18	33	ANT_1	63	NC
4	GPIO_19	34	GND	64	GND
5	WL_REG_ON	35	GND	65	VBAT
6	BT_REG_ON	36	BT_UART_RTS_N	66	VBAT
7	GND	37	BT_UART_CTS_N	67-73	GND
8	VDDIO	38	BT_UART_RXD	74	BT_PCM_IN
9	GND	39	BT_UART_TXD	75	BT_PCM_OUT
10	GND	40	GPIO_5	76	BT_PCM_CLK
11	GND	41	GPIO_4	77	BT_PCM_SYNC
12	BT_OUT	42	GPIO_7	78	GND
13	GND	43	GPIO_6	79	RF_SW_CTRL4
14	BT_IN	44	PCIE_PME_L	80	GND
15	GND	45	PCIE_PERST_L	81	RF_SW_CTRL12
16	RF_SW_CTRL5	46	PCIE_CLKREQ_L	82	BT_GPIO_5
17	GND	47	GND	83	BT_GPIO_4
18	GND	48	PCIE_RDN	84	BT_GPIO_2
19	ANT_0	49	PCIE_RDP	85	BT_GPIO_3
20	GND	50	GND	86	GPIO_3
21	GND	51	PCIE_REFCLKP	87	JTAG_SEL
22	BT_HOST_WAKE	52	PCIE_REFCLKN	88	GPIO_2
23	BT_DEV_WAKE	53	GND	89	GPIO_1
24	CLK_REQ	54	PCIE_TDN	90	GPIO_0
25	LPO_IN	55	PCIE_TDP	91	GPIO_8
26	BT_I2S_DO	56	GND	92	GPIO_9
27	BT_I2S_DI	57	VDDIO	93	GPIO_10
28	BT_I2S_CLK	58	NC	94	GPIO_11
29	BT_I2S_WS	59	NC	95-104	GND
30	GND	60	NC		

6.2 Pin Descriptions

Table 6 describes Type 1XA pins.

Table 6: Pin Descriptions

No.	Pin name	Type	Connection to IC Pin Name	Description
1	GND			Ground
2	GPIO_17	I/O	GPIO_17	Programmable GPIO Pin
3	GPIO_18	I/O	GPIO_18	Programmable GPIO Pin
4	GPIO_19	I/O	GPIO_19	Programmable GPIO Pin
5	WL_REG_ON	I	WL_REG_ON	Used by PMU to power up or power down the internal CYW54591 regulators used by the WLAN section. Also, when de-asserted, this pin holds the WLAN section in reset. This pin has an internal 200 kΩ pull-down resistor that is enabled by default. It can be disabled through programming.
6	BT_REG_ON	I	BT_REG_ON	Used by PMU to power up or power down the internal CYW54591 regulators used by the Bluetooth section. Also, when de-asserted, this pin holds the Bluetooth section in reset. This pin has an internal 200 kΩ pull-down resistor that is enabled by default. It can be disabled through programming.
7	GND			Ground
8	VDDIO	I	SYS_VDDIO WCC_VDDIO BT_VDDO VDDIO	IO supply
9	GND			Ground
10	GND			Ground
11	GND			Ground
12	BT_OUT			
13	GND			Ground
14	BT_IN			
15	GND			Ground
16	RF_SW_CTRL5	O	O	Programmable RF switch control lines. The control lines are programmable via the driver and NVRAM file.
17	GND			Ground
18	GND			Ground
19	ANT_0			RF Port for WLAN (2.4GHz & 5GHz) and BT
20	GND			Ground
21	GND			Ground
22	BT_HOST_WAKE	O	BT_HOST_WAKE	Host wake-up: Signal from the module to the host indicating that the module requires attention.
23	BT_DEV_WAKE	I	BT_DEV_WAKE	Bluetooth device wake-up: Signal from the host to the module indicating that the host requires attention.
24	CLK_REQ	I/O	CLK_REQ	Reference clock request (shared by BT and WLAN). If not used, this can be no-connect.
25	LPO_IN	I	LPO_IN	External sleep clock input (32.768 kHz)
26	BT_I2S_DO	I/O	BT_I2S_DO	I ² S data output
27	BT_I2S_DI	I/O	BT_I2S_DI	I ² S data input

No.	Pin name	Type	Connection to IC Pin Name	Description
28	BT_I2S_CLK	I/O	BT_I2S_CLK	I ² S clock, can be master (output) or slave (input).
29	BT_I2S_WS	I/O	BT_I2S_WS	I ² S WS, can be master (output) or slave (input).
30	GND			Ground
31	RF_SW_CTRL11	O	RF_SW_CTRL11	Programmable RF switch control lines. The control lines are programmable via the driver and NVRAM file.
32	GND			Ground
33	ANT_1			RF Port for WLAN (2.4 GHz & 5 GHz)
34	GND			Ground
35	GND			Ground
36	BT_UART_RTS_N	O	BT_UART_RTS_N	UART request-to-send. Active-low request-to-send signal for the HCI UART interface. BT LED control pin.
37	BT_UART_CTS_N	I	BT_UART_CTS_N	UART clear-to-send. Active-low clear-to-send signal for the HCI UART interface.
38	BT_UART_RXD	I	BT_UART_RXD	UART serial input. Serial data input for the HCI UART interface.
39	BT_UART_TXD	O	BT_UART_TXD	UART serial output. Serial data output for the HCI UART interface.
40	GPIO_5		GPIO_5	Programmable GPIO pins.
41	GPIO_4		GPIO_4	
42	GPIO_7		GPIO_7	
43	GPIO_6		GPIO_6	
44	PCIE_PME_L	OD	PCIE_PME_L	PCI power management event output. Used to request a change in the device.
45	PCIE_PERST_L	I	PCIE_PERST_L	PCIe System Reset. This input is the PCIe reset as defined in the PCIe base specification version 1.1. PCIE_PERST_L pad excludes internal pull-up.
46	PCIE_CLKREQ_L	OD	PCIE_CLKREQ_L	PCIe clock request signal which indicates when the REFCLK to the PCIe interface can be gated. <ul style="list-style-type: none"> • 1 = the clock can be gated. • 0 = the clock is required.
47	GND	-	-	Ground
48	PCIE_RDN	I	PCIE_RDN0	Receiver differential pair (x1 lane).
49	PCIE_RDP	I	PCIE_RDP0	Receiver differential pair (x1 lane).
50	GND	-	-	Ground
51	PCIE_REFCLKP	I	PCIE_REFCLKP	PCIe Differential Clock inputs (negative and positive). 100 MHz differential.
52	PCIE_REFCLKN	I	PCIE_REFCLKN	
53	GND	-	-	Ground
54	PCIE_TDN	O	PCIE_TDN0	Transmitter differential pair (x1 lane).
55	PCIE_TDP	O	PCIE_TDP0	
56	GND			Ground
57	VDDIO	I	VDDIO	IO supply
58	NC			No Connect
59	NC			No Connect
60	NC			No Connect

No.	Pin name	Type	Connection to IC Pin Name	Description
61	NC			No Connect
62	NC			No Connect
63	NC			No Connect
64	GND			Ground
65	VBAT		SR_VDDBAT5V	VBAT supply
66			LDO_VDDBAT5V	
67-73	GND			Ground
74	BT_PCM_IN	I	BT_PCM_IN	PCM data input.
75	BT_PCM_OUT	O	BT_PCM_OUT	PCM data output.
76	BT_PCM_CLK	I/O	BT_PCM_CLK	PCM clock; can be master (output) or slave (input).
77	BT_PCM_SYNC	I/O	BT_PCM_SYNC	PCM sync; can be master (output) or slave (input).
78	GND	-	-	Ground
79	RF_SW_CTRL4	O	RF_SW_CTRL4	Programmable RF switch control lines. The control lines are programmable via the driver and NVRAM file.
80	GND	-	-	Ground
81	RF_SW_CTRL12	O	RF_SW_CTRL12	Programmable RF switch control lines. The control lines are programmable via the driver and NVRAM file.
82	BT_GPIO_5	I/O	BT_GPIO_5	Bluetooth general-purpose I/O.
83	BT_GPIO_4	I/O	BT_GPIO_4	
84	BT_GPIO_2	I/O	BT_GPIO_2	
85	BT_GPIO_3	I/O	BT_GPIO_3	
86	GPIO_3	I/O	GPIO_3	Programmable GPIO pins.
87	JTAG_SEL	I/O	JTAG_SEL	JTAG select pull high to select the JTAG interface. If the JTAG interface is not used this pin may be left floating or connected to ground.
88	GPIO_2	I/O	GPIO_2	Programmable GPIO pins.
89	GPIO_1	I/O	GPIO_1	
90	GPIO_0	I/O	GPIO_0	
91	GPIO_8	I/O	GPIO_8	
92	GPIO_9	I/O	GPIO_9	
93	GPIO_10	I/O	GPIO_10	
94	GPIO_11	I/O	GPIO_11	
95-104	GND			Ground

7 Absolute Maximum Ratings

The minimum and maximum ratings are shown in **Table 7**.

Table 7: Absolute Maximum Ratings

Parameter		Minimum	Maximum	Unit
Storage Temperature		-40	+85	°C
Supply Voltage	VBAT	-0.5	+6.0	V
	VDDIO	-0.5	+3.9	V



Stresses in excess of the absolute ratings may cause permanent damage. Functional operation is not implied under these conditions. Exposure to absolute ratings for extended periods of time may adversely affect reliability. No damage assuming only one parameter is set at limit at a time with all other parameters are set within operating condition.

8 Operating Conditions

The operating conditions are shown **Table 8**.

Table 8: Operating Conditions

Parameter		Minimum	Typical	Maximum	Unit
Operating Temperature Range		-40	25	85	°C
Specification Temperature		-10	25	70	°C
Operating Voltage	VBAT	3.0	3.3	4.8	V
	VDDIO	1.62	1.8 or 3.3	3.63	V

9 External LPO_IN Signal Requirements

The external LPO_IN signal requirements are shown in **Table 9**.

Table 9: External LPO_IN Signal Requirements

Parameter	External LPO_IN Clock	Unit
Nominal input frequency	32.768	kHz
Frequency accuracy	+/-250	ppm
Duty cycle	30-70	%
Input signal amplitude	200 - 3300	mV, p-p
Signal type	Square-wave or sinewave	-
Input impedance ¹	> 100k	Ω
	< 5	pF
Clock jitter (during initial start-up)	<10,000	ppm

¹ When power is applied or switch off

10 I/O States

The following notations are used in I/O State Table.

- **I**: Input signal
- **O**: Output signal
- **I/O**: Input/Output signal
- **PU** = Pulled up
- **PD** = Pulled down
- **NoPull** = Neither pulled up nor pulled down
- Where applicable, the default value is shown in bold brackets (for example, [default value])

Table 10: IO State Table

Name	I/O	Keeper	Active Mode	Low Power State/Sleep (All Power Present)	Power-down (BT_REG_ON and WL_REG_ON Held Low)	Out-of-Reset: Before SW Download (BT_REG_ON High, WL_REG_ON High)	Power-down (WL_REG_ON High and BT_REG_ON=0) and VDDIOs Are Present	Power Rail
WL_REG_ON BT_REG_ON	I	N	I: PD Pull-down can be disabled	I: PD Pull-down can be disabled	I: PD (of 200K)	I: PD (of 200K)	I: PD (of 200K)	
GPIO_0	I/O	Y	I/O: PU, PD, NoPull Programmable [PD]	I/O: PU, PD, NoPull Programmable [PD]	High-Z, NoPull	I: PD	I: PD	VDDIO
GPIO_1	I/O	Y	I/O: PU, PD, NoPull Programmable [NoPull]	I/O: PU, PD, NoPull Programmable [NoPull]	High-Z, NoPull	I: NoPull	I: NoPull	VDDIO
GPIO_2	I/O	Y	I/O: PU, PD, NoPull Programmable [NoPull]	I/O: PU, PD, NoPull Programmable [NoPull]	High-Z, NoPull	I: NoPullb	I: NoPull	VDDIO
GPIO_3	I/O	Y	I/O: PU, PD, NoPull Programmable [NoPull]	I/O: PU, PD, NoPull Programmable [NoPull]	High-Z, NoPull	I: NoPullb	I: NoPull	VDDIO
GPIO_4	I/O	Y	I/O: PU, PD, NoPull Programmable [NoPull]	I/O: PU, PD, NoPull Programmable [NoPull]	High-Z, NoPull	I: NoPullb	I: NoPull	VDDIO
GPIO_5	I/O	Y	I/O: PU, PD, NoPull Programmable [NoPull]	I/O: PU, PD, NoPull Programmable [NoPull]	High-Z, NoPull	I: NoPullb	I: NoPull	VDDIO
GPIO_6	I/O	Y	I/O: PU, PD, NoPull Programmable [NoPull]	I/O: PU, PD, NoPull Programmable [NoPull]	High-Z, NoPull	I: NoPullb	I: NoPull	VDDIO
GPIO_7	I/O	Y	I/O: PU, PD, NoPull Programmable [NoPull]	I/O: PU, PD, NoPull Programmable [NoPull]	High-Z, NoPull	I: NoPull	I: NoPull	VDDIO
GPIO_8	I/O	Y	I/O: PU, PD, NoPull	I/O: PU, PD, NoPull	High-Z, NoPull	I: NoPull	I: NoPull	VDDIO

Name	I/O	Keeper	Active Mode	Low Power State/Sleep (All Power Present)	Power-down (BT_REG_ON and WL_REG_ON Held Low)	Out-of-Reset: Before SW Download (BT_REG_ON High, WL_REG_ON High)	Power-down (WL_REG_ON High and BT_REG_ON=0) and VDDIOs Are Present	Power Rail
			Programmable [NoPull]	Programmable [NoPull]				
GPIO_9	I/O	Y	I/O: PU, PD, NoPull Programmable [PU]	I/O: PU, PD, NoPull Programmable [NoPull]	I: PU	I: PU	I:PU	VDDIO
GPIO_10	I/O	Y	I/O: PU, PD, NoPull Programmable [NoPull]	I/O: PU, PD, NoPull Programmable [NoPull]	High-Z, NoPull	I: NoPull	I: NoPull	VDDIO
GPIO_11	I/O	Y	I/O: PU, PD, NoPull Programmable [PU]	I/O: PU, PD, NoPull Programmable [PU]	I: PU	I: PU	I:PU	VDDIO
GPIO_17	I/O	Y	I/O: PU, PD, NoPull Programmable [NoPull]	I/O: PU, PD, NoPull Programmable [NoPull]	High-Z, NoPull	I: NoPull	I: NoPull	VDDIO
GPIO_18	I/O	Y	I/O: PU, PD, NoPull Programmable [NoPull]	I/O: PU, PD, NoPull Programmable [NoPull]	High-Z, NoPull	I: NoPull	I: NoPull	VDDIO
GPIO_19	I/O	Y	I/O: PU, PD, NoPull Programmable [NoPull]	I/O: PU, PD, NoPull Programmable [NoPull]	High-Z, NoPull	I: NoPull	I: NoPull	VDDIO
RF_SW_CTRL_X	O	N	O: No Pull	O: No Pull	High-Z, NoPull	O: NoPull	O: NoPull	VDDIO_RF
CLK_REQ	O	Y	Open drain or push-pull (programmable) Active high.	Open drain or push-pull (programmable). Active high.	High-Z, NoPull	Open drain. Active high	Open drain. Active high	BT_VDDO
BT_HOST_WAKE	O	Y	Input/Output; PU, PD, NoPull (programmable)	Input/Output; PU, PD, NoPull (programmable)	High-Z, NoPull	Input, PU	Input, PD	BT_VDDO
BT_DEV_WAKE	I	Y	Input/Output; PU, PD, NoPull (programmable)	Input/Output; PU, PD, NoPull (programmable)	High-Z, NoPull	Input, PD	Input, PD	BT_VDDO
BT_GPIO_2 BT_GPIO_3	I/O	Y	Input/Output; PU, PD, NoPull (programmable)	Input/Output; PU, PD, NoPull (programmable)	High-Z, NoPull	Input, PD	Input, PD	BT_VDDO
BT_GPIO_4 BT_GPIO_5	I/O	Y	Input/Output; PU, PD, NoPull (programmable)	Input/Output; PU, PD, NoPull (programmable)	High-Z, NoPull	Input, PU	Input, PU	BT_VDDO
BT_UART_CS_N	I	Y	Input, NoPull	Input, NoPull	High-Z, NoPull	Input, PU	Input, PU	BT_VDDO
BT_UART_RS_N	O	Y	Output, NoPull	Output, NoPull	High-Z, NoPull	Input, PU	Input, PU	BT_VDDO
BT_UART_RXD	I	Y	Input, NoPull	Input, NoPull	High-Z, NoPull	Input, PU	Input, PU	BT_VDDO
BT_UART_TXD	O	Y	Output, NoPull	Output, NoPull	High-Z, NoPull	Input, PU	Input, PU	BT_VDDO

Name	I/O	Keeper	Active Mode	Low Power State/Sleep (All Power Present)	Power-down (BT_REG_ON and WL_REG_ON Held Low)	Out-of-Reset: Before SW Download (BT_REG_ON High. WL_REG_ON High)	Power-down (WL_REG_ON High and BT_REG_ON=0) and VDDIOs Are Present	Power Rail
BT_PCM_CLK	I/O	Y	Input, NoPull	Input, NoPull	High-Z, NoPull	Input, PD	Input, PD	BT_VDDO
BT_PCM_IN	I/O	Y	Input, NoPull	Input, NoPull	High-Z, NoPull	Input, PD	Input, PD	BT_VDDO
BT_PCM_OUT	I/O	Y	Input, NoPull	Input, NoPull	High-Z, NoPull	Input, PD	Input, PD	BT_VDDO
BT_PCM_SYNC	I/O	Y	Input, NoPull	Input, NoPull	High-Z, NoPull	Input, PD	Input, PD	BT_VDDO
BT_I2S_CLK	I/O	Y	Input, NoPull	Input, NoPull	High-Z, NoPull	High-Z, NoPull	High-Z, NoPull	BT_VDDO
BT_I2S_DO	I/O	Y	Output, NoPull	Output, NoPull	High-Z, NoPull	Input, PD	Input, PD	BT_VDDO
BT_I2S_DI	I/O	Y	Input, NoPull	Input, NoPull	High-Z, NoPull	Input, PD	Input, PD	BT_VDDO
BT_I2S_WS	I/O	Y	Input, NoPull	Input, NoPull	High-Z, NoPull	High-Z, NoPull	High-Z, NoPull	BT_VDDO

11 Power Sequences

This section describes the Power-On and Power-Off Sequences along with their parameters.

11.1 Power-On Sequence

For this sequence:

- VBAT and VDDIO should not rise 10%-90% faster than 40 microseconds.
- VBAT should be up before or at the same time as VDDIO. VDDIO should NOT be present fast or be held high before VBAT is high.
- WL_REG_ON and BT_REG_ON should be up after sleep clock oscillation is stabilized.
- Please proceed reset by WL_REG_ON and BT_REG_ON until it starts normally if it doesn't wake from sleep properly, or it is presented with uncertain status.
- Please keep repeats power off sequence and power on sequence several times until it started normally.
- The CYW54591 has an internal Power-On reset (POR) circuit. The device will be held in reset for a maximum of 110 ms after internal regulators and VDDIO have passed the POR threshold. Wait at least 150 ms after WL_REG_ON is driven high before initiating PCIe accesses.

Figure 4 shows the power-on sequence for WLAN On and BT ON.

Figure 4: Power-On Sequence for WLAN ON and BT ON

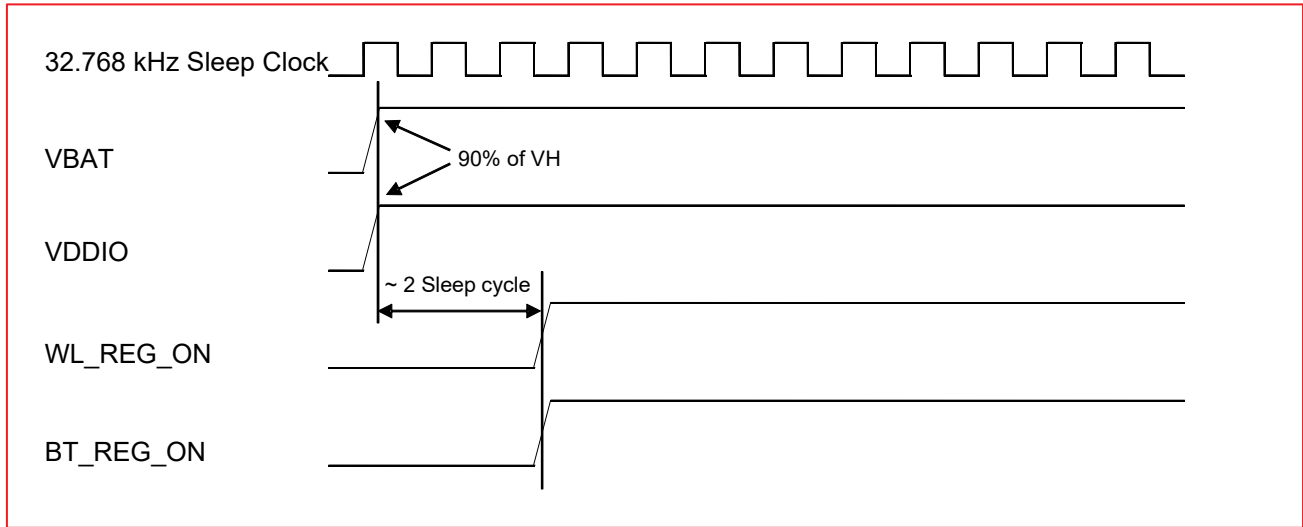


Figure 5 shows the power-on sequence for WLAN OFF and BT OFF.

Figure 5: Power-On Sequence for WLAN OFF and BT OFF

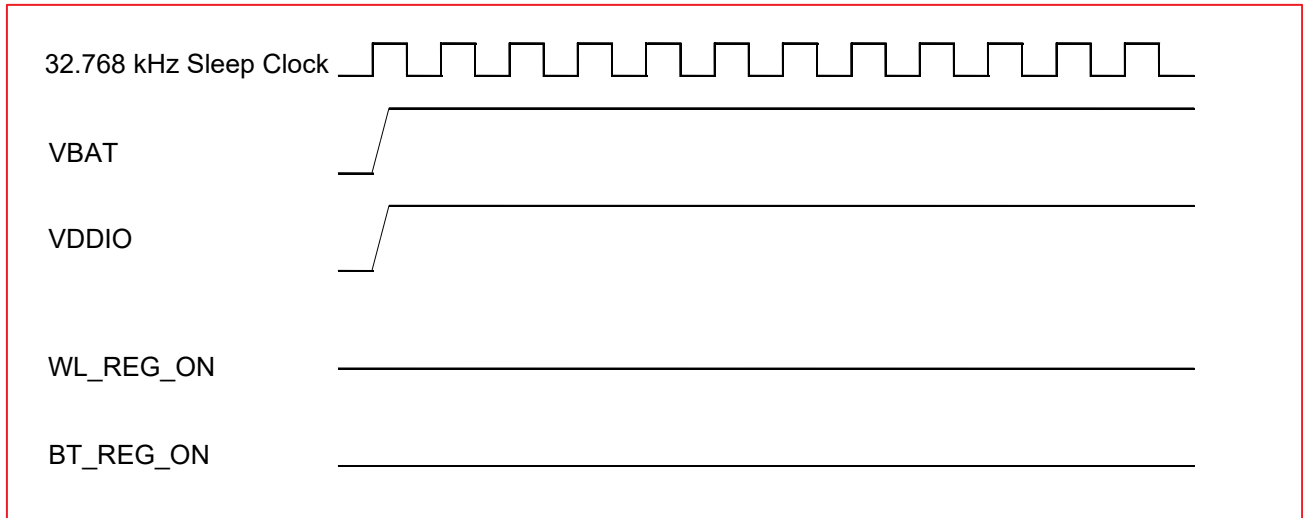


Figure 6 shows the power-on sequence for WLAN ON and BT OFF.

Figure 6: Power-On Sequence for WLAN ON and BT OFF

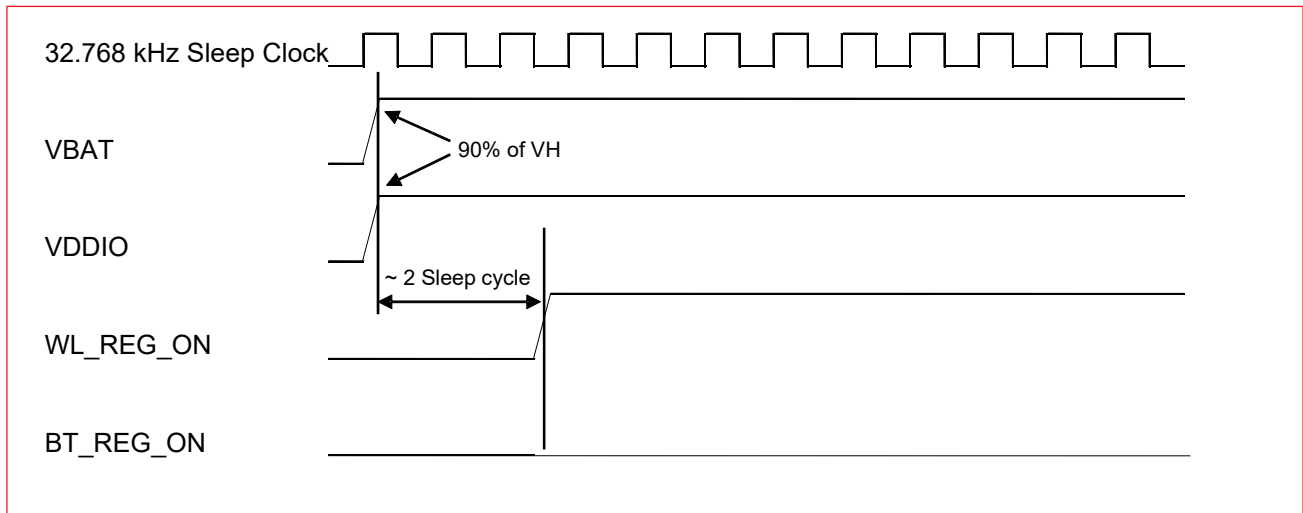
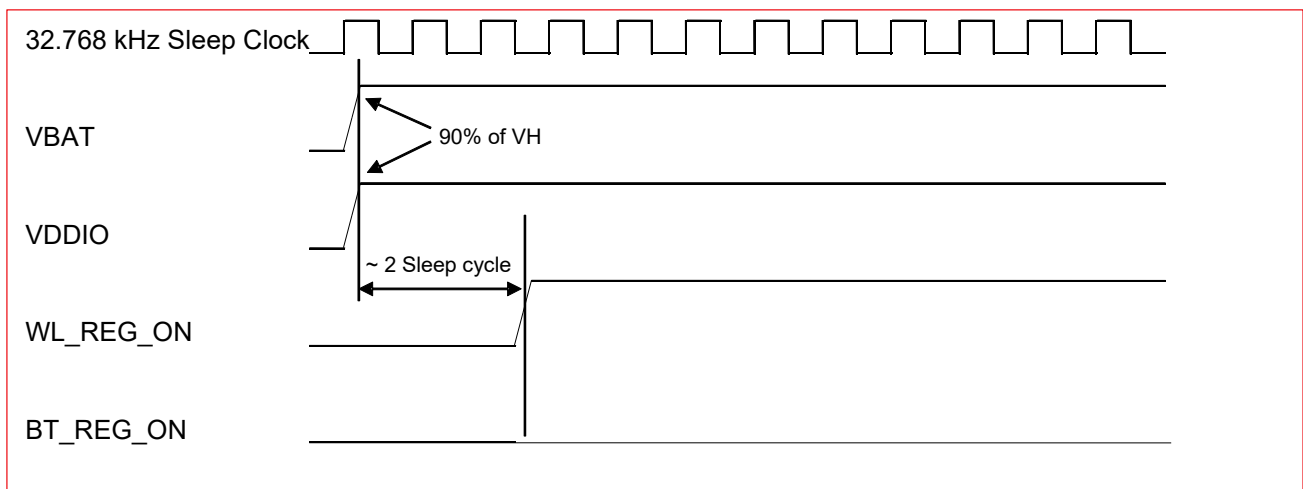


Figure 7 shows the power-on sequence for WLAN OFF and BT ON.

Figure 7: Power-On Sequence for WLAN OFF and BT ON



11.2 Power-Off Sequence

For power-off sequence:

- VDDIO should be down before or at the same time as VBAT. VBAT should NOT be down earlier than VDDIO low. VDDIO becomes low state is prior to VBAT low.
- VBAT and VDDIO should be down after WL_REG_ON and BT_REG_ON are low. Waiting time from REG_ON down to power supply off is not prescribed.

Figure 8 shows the power-off sequence for WLAN ON and BT ON.

Figure 8: Power-Off Sequence for WLAN ON and BT ON

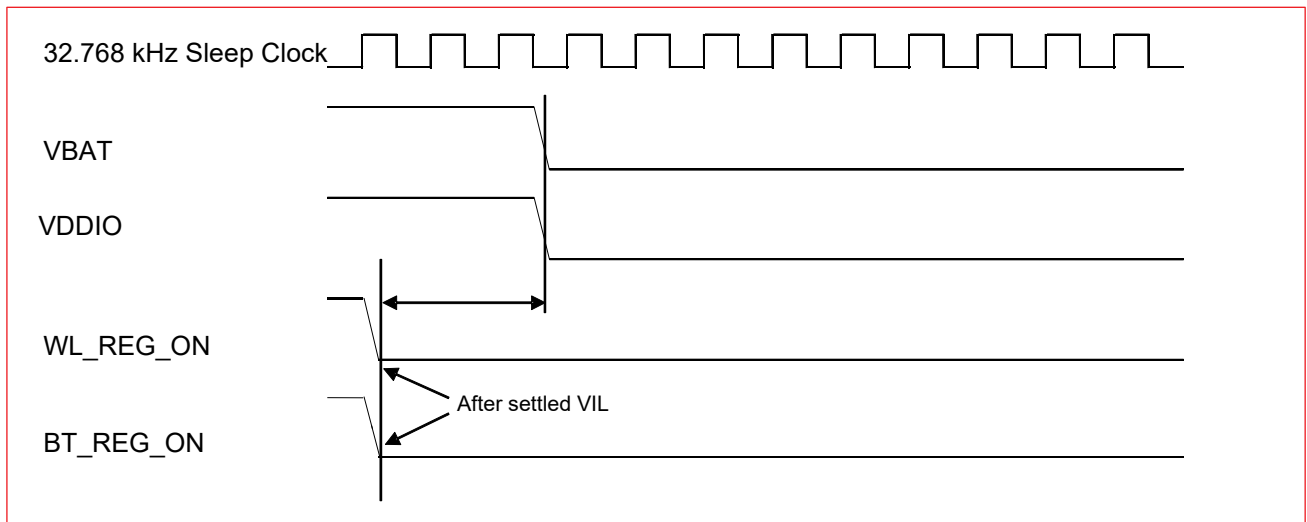


Figure 9 shows the power-off sequence for WLAN OFF and BT OFF is shown in.

Figure 9: Power-Off Sequence for WLAN OFF and BT OFF

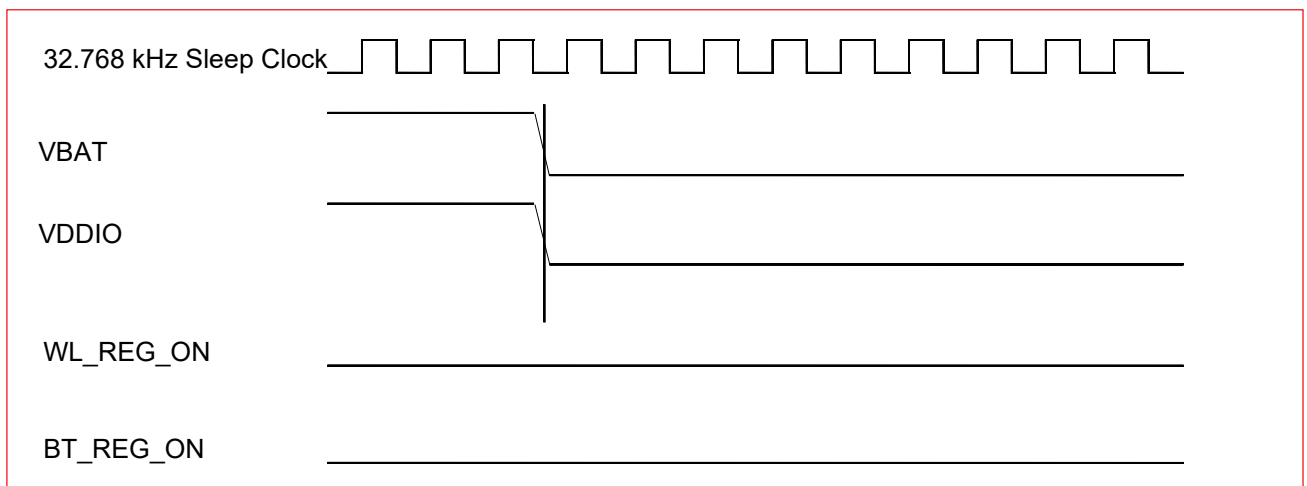


Figure 10 shows the power-off sequence for WLAN ON and BT OFF.

Figure 10: Power-Off Sequence for WLAN ON and BT OFF

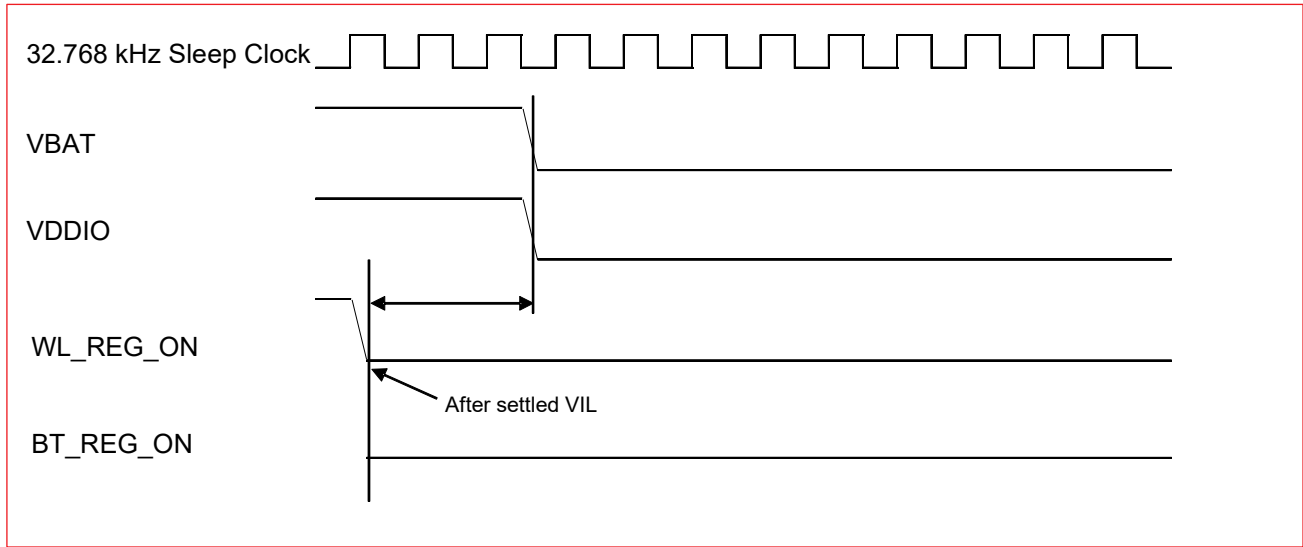
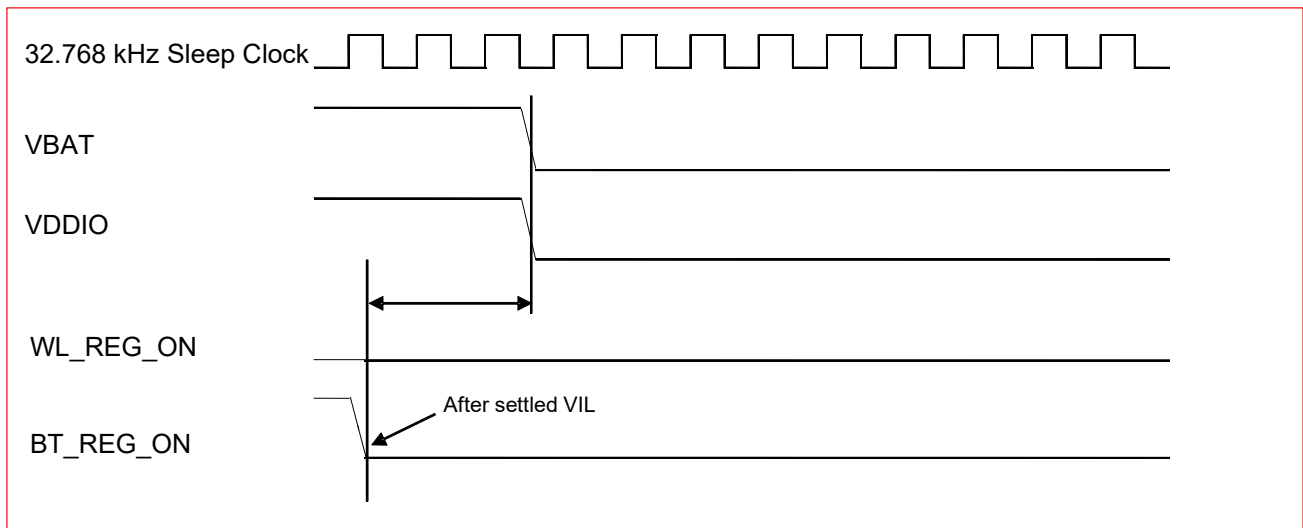


Figure 11 shows the power-off sequence for WLAN OFF and BT ON.

Figure 11: Power-Off Sequence for WLAN OFF and BT ON



12 Interface Timing and AC Characteristics

This section has sequence diagrams for Bluetooth UART timing, Bluetooth startup signaling sequence, Bluetooth PCM interface timing and Bluetooth I²S interface timing.

12.1 Bluetooth UART Timing

Bluetooth UART timing diagram and parameters are shown in **Figure 12** and **Table 11**.

Figure 12: UART Timing Diagram

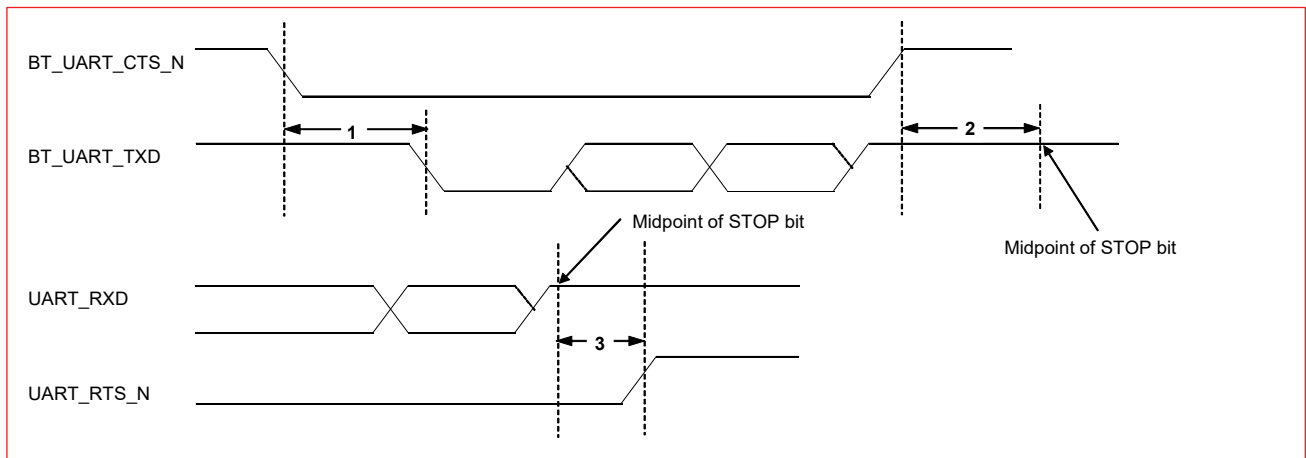


Table 11: UART Timing Parameters

Reference	Description	Minimum	Typical	Maximum	Unit
1	Delay time, UART_CTS_N low to UART_TXD valid			1.5	Bit periods
2	Setup time, UART_CTS_N high before midpoint of stop bit			0.5	Bit periods
3	Delay time, midpoint of stop bit to UART_RTS_N high			0.5	Bit periods

12.2 Bluetooth Startup Signaling Sequence

Bluetooth startup signaling sequence graph and its parameters is shown in **Figure 13** and **Table 12**.

Figure 13: Bluetooth Startup Signaling Sequence Graph

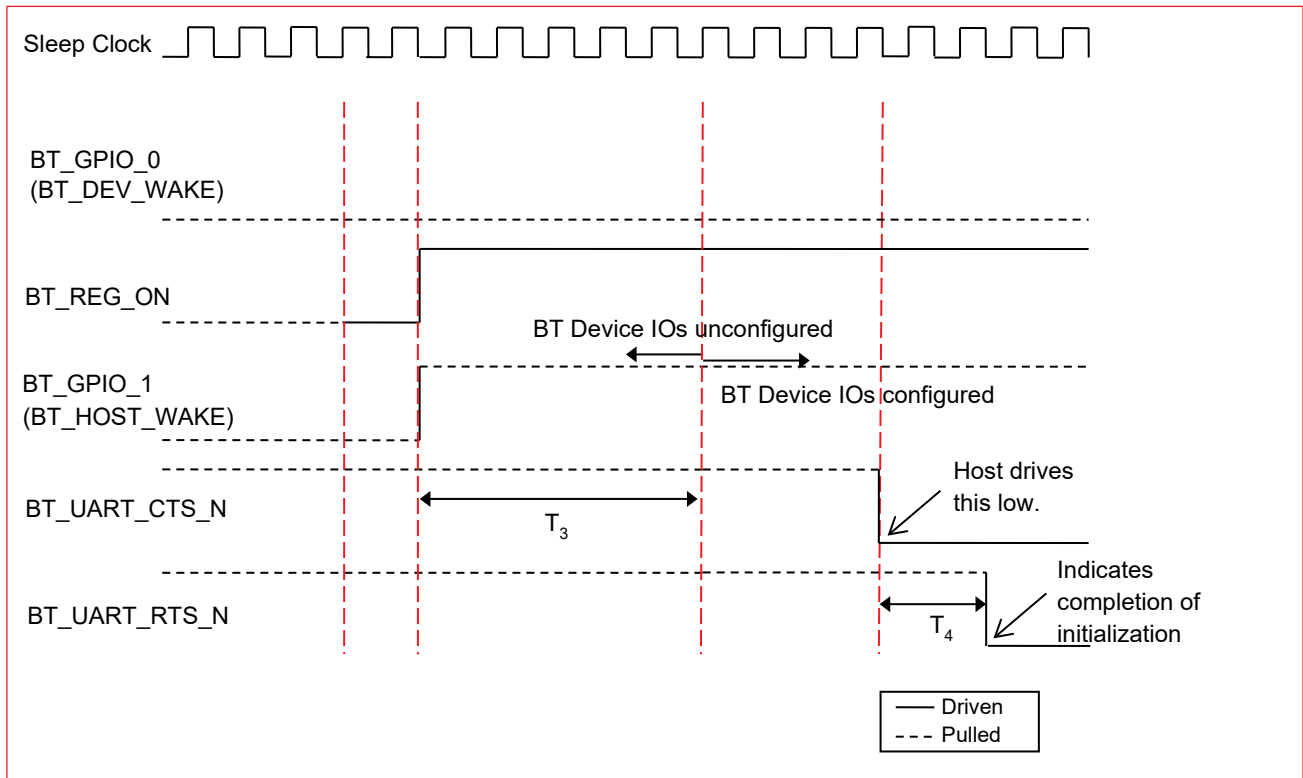


Table 12: Bluetooth Startup Signaling Sequence Parameters

Reference	Description	Minimum	Typical	Maximum	Unit
T ₃	Time for the BT device to settle its IOs after BT_REG_ON is asserted.			40.0	ms
T ₄	Time for the BT device to drive UART_RTS_N low after the host drives UART_CTS_N low			10.0	ms

12.3 Bluetooth PCM Timing

This section describes data formatting, wideband speech support, and various sync modes.

12.3.1 Data Formatting

The IC used in the module may be configured to generate and accept several different data formats. For conventional narrowband speech mode, the IC uses 13 of the 16 bits in each PCM frame. The location and order of these 13 bits can be configured to support various data formats on PCM interface. The remaining three bits are ignored on the input and may be filled with 0s, 1s, a sigh bit, or a programmed value on the output. The default format is 13-bit 2’s complement data, left justified, and clocked MSB first.

12.3.2 Wideband Speech Support

When the host encodes wideband speech (WBS) packets in transparent mode, the encoded packets are transferred over the PCM bus for an eSCO voice connection. In this mode, the PCM bus is typically configured in master mode for a 4 kHz sync rate with 16-bit samples, resulting in a 64-kbps bit rate. The IC also supports slave transparent mode using a proprietary rate-matching scheme. IN SBC-code mode, linear 16-bit data at 16 kHz (256 kbps rate) is transferred over the PCM bus.

12.3.3 Short Frame Sync (Master Mode)

Figure 14 and **Table 13** show the short frame sync signal and its parameters in master mode.

Figure 14: Short Frame Sync Signal - Master Mode

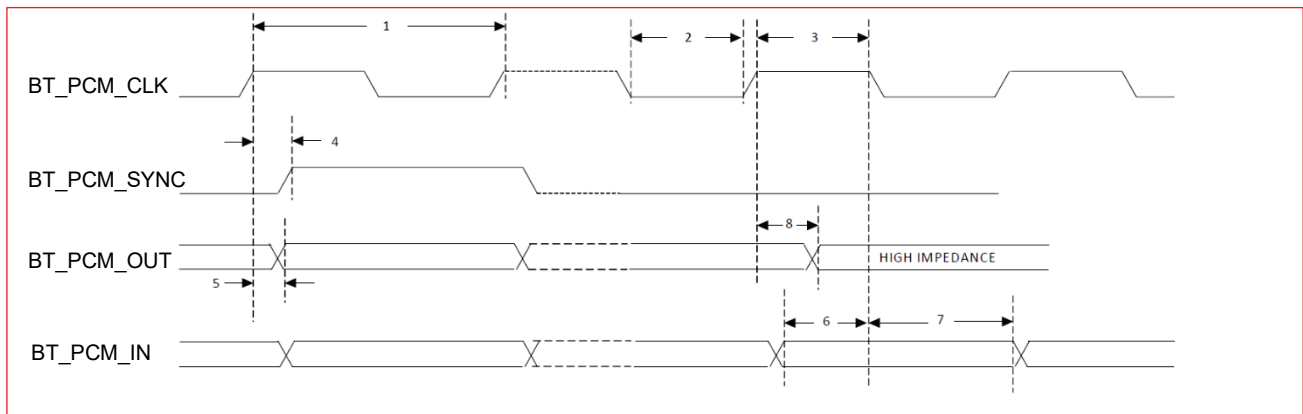


Table 13: Short Frame Sync Signal Parameters - Master Mode

Reference	Description	Minimum	Typical	Maximum	Unit
1	PCM bit clock frequency			12.0	MHz
2	PCM bit clock High	41.0			ns
3	PCM bit clock Low	41.0			ns
4	PCM_SYNC delay	0		25.0	ns
5	PCM_OUT delay	0		25.0	ns
6	PCM_IN setup	8			ns
7	PCM_IN hold	8			ns
8	Delay from rising edge of PCM_BCLK during last bit period to PCM_OUT becoming high impedance.	0		25.0	ns

12.3.4 Short Frame Sync (Slave Mode)

Figure 15 and Table 14 show the short frame sync signal and its parameters in slave mode.

Figure 15: Short Frame Sync Signal - Slave Mode

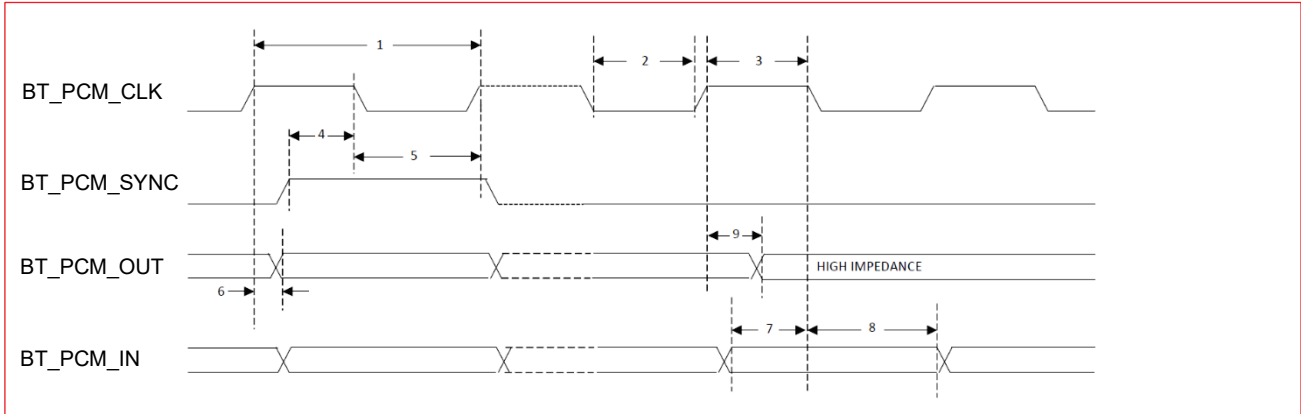


Table 14: Short Frame Sync Signal Parameters - Slave Mode

Reference	Description	Minimum	Typical	Maximum	Unit
1	PCM bit clock frequency			12.0	MHz
2	PCM bit clock High	41.0			ns
3	PCM bit clock Low	41.0			ns
4	PCM_SYNC setup	8.0			ns
5	PCM_SYNC hold	8.0			ns
6	PCM_OUT delay	0		25.0	ns
7	PCM_IN setup	8.0			ns
8	PCM_IN hold	8.0			ns
9	Delay from rising edge of PCM_BCLK during last bit period to PCM_OUT becoming high impedance.	0		25.0	ns

12.3.5 Long Frame Sync (Master Mode)

Figure 16 and Table 15 show the long frame sync signal and its parameters in master mode.

Figure 16: Long Frame Sync Signal - Master Mode

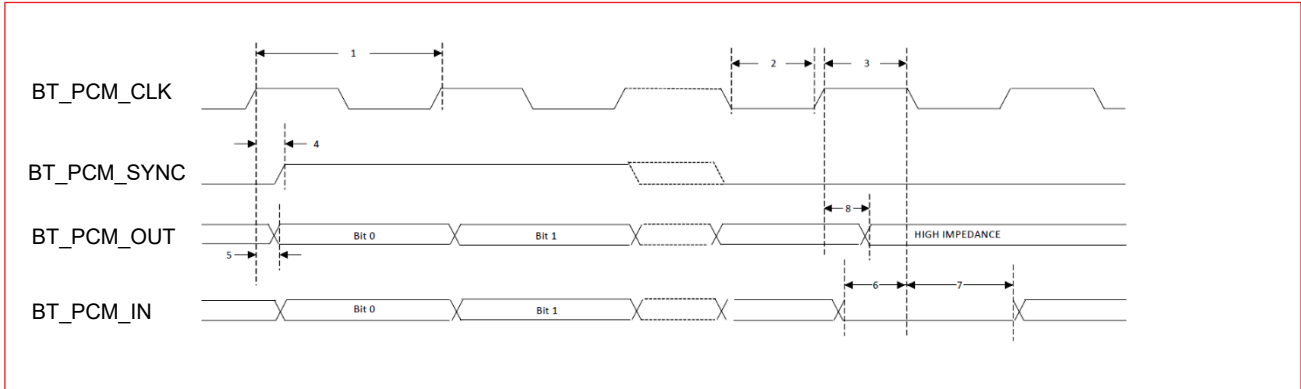


Table 15: Long Frame Sync Signal Parameters - Master Mode

Reference	Description	Minimum	Typical	Maximum	Unit
1	PCM bit clock frequency			12.0	MHz
2	PCM bit clock High	41.0			ns
3	PCM bit clock Low	41.0			ns
4	PCM_SYNC delay	0		25.0	ns
5	PCM_OUT delay	0		25.0	ns
6	PCM_IN setup	8.0			ns
7	PCM_IN hold	8.0			ns
8	Delay from rising edge of PCM_BCLK during last bit period to PCM_OUT becoming high impedance.	0		25.0	ns

12.3.6 Long Frame Sync (Slave Mode)

Figure 17 and Table 16 show the long frame sync signal and its parameters in slave mode data.

Figure 17: Long Frame Sync Signal - Slave Mode

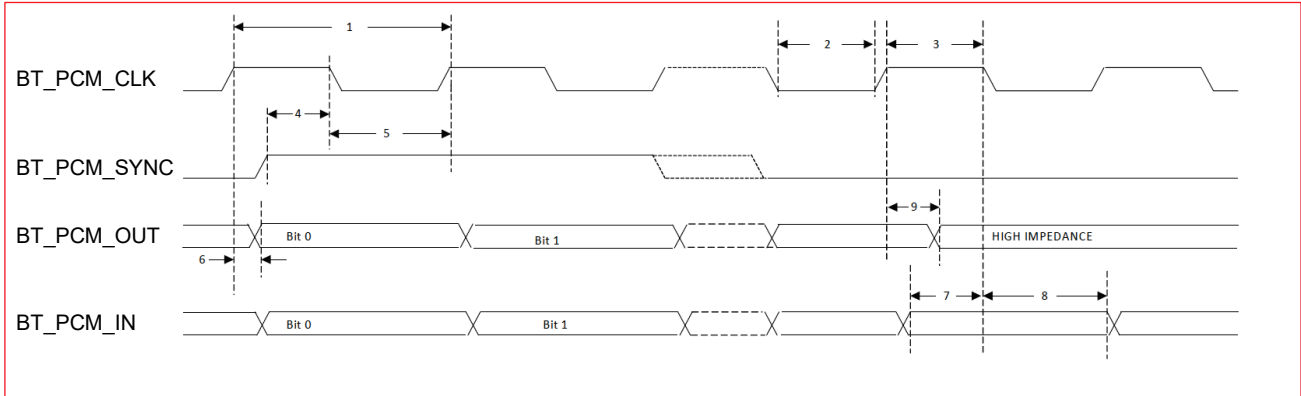


Table 16: Long Frame Sync Signal Parameters - Slave Mode

Reference	Description	Minimum	Typical	Maximum	Unit
1	PCM bit clock frequency			12.0	MHz
2	PCM bit clock High	41.0			ns
3	PCM bit clock Low	41.0			ns
4	PCM_SYNC Setup	8.0			ns
5	PCM_SYNC hold	8.0			ns
6	PCM_OUT delay	0		25.0	ns
7	PCM_IN Setup	8.0			ns
8	PCM_IN Hold	8.0			ns
9	Delay from rising edge of PCM_BCLK during last bit period to PCM_OUT becoming high impedance.	0		25.0	ns

12.4 Bluetooth I²S Interface Timing

The IC used in the module supports I²S format. The module supports only PCM digital audio ports through I²S format.

The I²S signals are:

- I²S clock: I²S SCK (Module pin: BT_PCM_CLK)
- I²S Word Select: I²S WS (Module pin: BT_PCM_SYNC)
- I²S Data Out: I²S SDO (Module pin: BT_PCM_OUT)
- I²S Data In: I²S SDI (Module pin: BT_PCM_IN)

I²S SCK and I²S WS become outputs in master mode and inputs in slave mode, while I²S SDO always stays as an output. The channel word length is 16 bits, and the data is justified so that the MSB of the left-channel data is aligned with the MSB of the I²S bus, per the I²S specification. The MSB of each data word is transmitted one bit clock cycle after the I²S WS transition, synchronous with the falling edge of bit clock. Left-channel data is transmitted when I²S WS is low, and right-channel data is transmitted when I²S WS is high. Data bits sent by the CYW89335 are synchronized with the falling edge of I²S_SCK and should be sampled by the receiver on the rising edge of I²S_SCK.

The clock rate in master mode is either of the following:

- 48 kHz x 32 bits per frame = 1.536 MHz
- 48 kHz x 50 bits per frame = 2.400 MHz

The master clock is generated from the input reference clock using a N/M clock divider.



In the slave mode, any clock rate is supported to a maximum of 3.072 MHz

Table 17: Timing for I²S Transmitters and Receivers

	Transmitter				Receiver				Notes
	Lower Limit		Upper Limit		Lower Limit		Upper Limit		
	Minimum	Maximum	Minimum	Maximum	Minimum	Maximum	Minimum	Maximum	
Clock Period T	T _{tr}				T _r				a
Master Mode: Clock generated by transmitter or receiver									
HIGH t _{HC}	0.35T _{tr}				0.35T _{tr}				b
LOW t _{LC}	0.35T _{tr}				0.35T _{tr}				b
Slave Mode: Clock accepted by transmitter or receiver									
HIGH t _{HC}		0.35T _{tr}				0.35T _{tr}			c
LOW t _{LC}		0.35T _{tr}				0.35T _{tr}			c
Rise time t _{RC}			0.15T _{tr}						d
Transmitter									
Delay t _{dtr}				0.8T					e
Hold time t _{htr}	0								d
Receiver									

	Transmitter				Receiver				Notes
	Lower Limit		Upper Limit		Lower Limit		Upper Limit		
	Minimum	Maximum	Minimum	Maximum	Minimum	Maximum	Minimum	Maximum	
Setup time t_{sr}						0.2Tr			f
Hold time t_{hr}						0			f

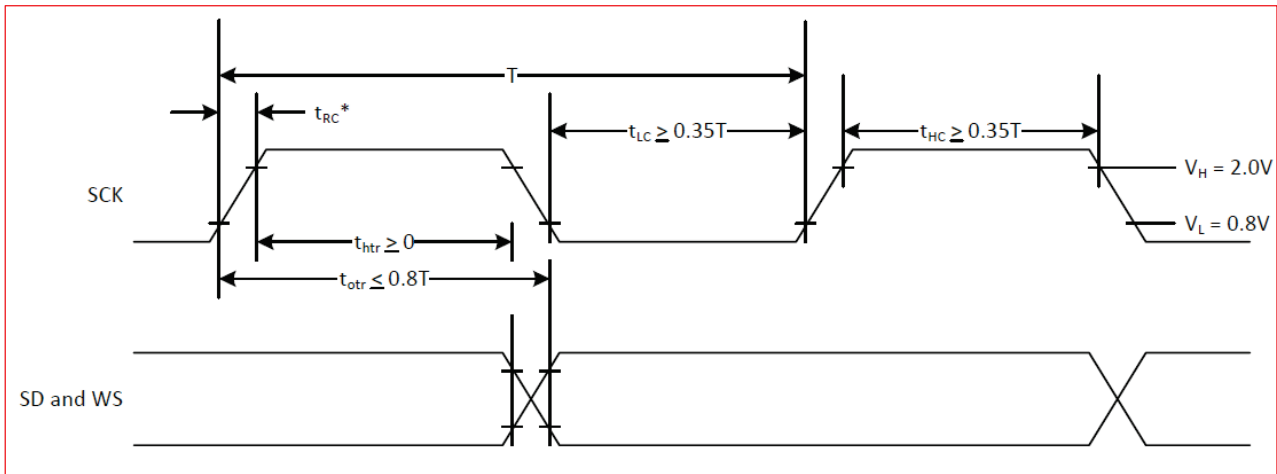
- a) The system clock period T must be greater than T_{tr} and T_r because both the transmitter and receiver have to be able to handle the data transfer rate.
- b) At all data rates in master mode, the transmitter or receiver generates a clock signal with a fixed mark/space ratio. For this reason, t_{HC} and t_{LC} specified with respect to T .
- c) In slave mode, the transmitter and receiver need a clock signal with minimum HIGH and LOW periods so that they can detect the signal. So long as the minimum periods are greater than $0.35T_{tr}$ any clock that meets the requirements can be used.
- d) Because the delay (t_{dtr}) and the maximum transmitter speed (defined by T_{tr}) are related, a fast transmitter driven by a slow clock edge can result in t_{dtr} not exceeding t_{RC} which means t_{thr} becomes zero or negative. Therefore, the transmitter has guarantee that t_{thr} is greater than or equal to zero, so long as the clock rise-time t_{RC} is not more than t_{RC} where t_{RCmax} is not less than $0.15T_{tr}$.
- e) To allow data to be clocked out on a falling edge, the delay is specified with respect to the rising edge of the clock signal and T , always giving the receiver sufficient setup time.
- f) The data setup and hold time must not be less than the specified receiver setup and hold time.



The time periods specified in below figures are defined by the transmitter speed. The receiver specifications must match transmitter performance.

Figure 18 shows the I²S transmitters timing sequence.

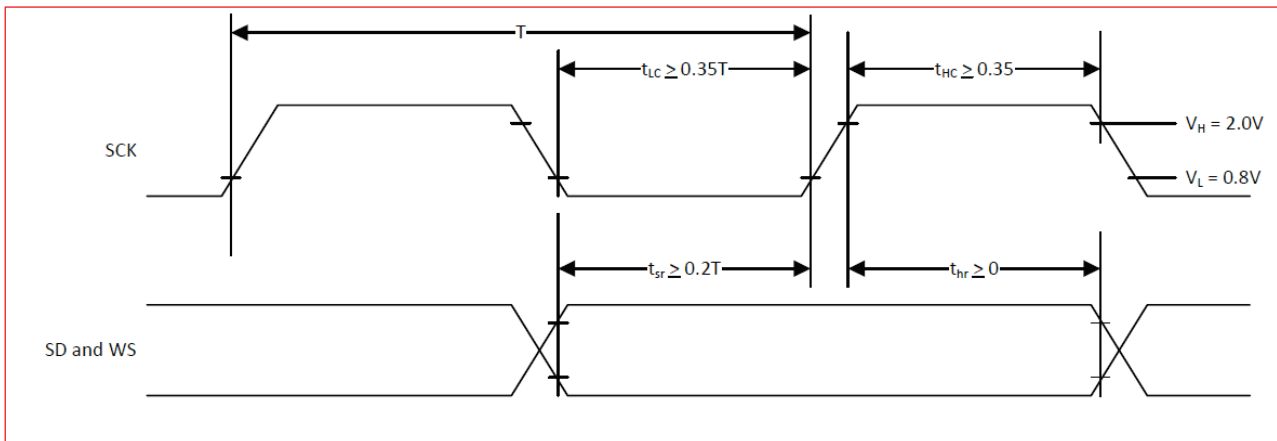
Figure 18: I²S Transmitters Timing Sequence



- T = Clock period
- T_{tr} = Minimum allowed clock period for transmitter
- $T = T_{tr}$
- t_{RC} is only relevant for transmitters in slave mode.

Figure 19 shows the I²S receivers timing sequence.

Figure 19: I²S Receivers Timing Sequence



- T = Clock period
- T_r = Minimum allowed clock period for transmitter
- $T > T_r$

13 Electrical Characteristics

13.1 DC/RF Characteristics for IEEE 802.11b - 2.4 GHz

Conditions: 25 °C, VBAT = 3.3V, 11 Mbps mode unless otherwise specified.

Table 18: DC/RF Characteristics for IEEE 802.11b - 2.4 GHz

Items	Contents			
Specification	IEEE 802.11b - 2.4 GHz			
Mode	DSSS / CCK			
Channel Frequency	2412 to 2472 MHz (5 MHz)			
Data Rate	1, 2, 5.5, 11 Mbps			
Current Consumption	Minimum	Typical	Maximum	Unit
• Tx mode		370	470	mA
• Rx mode		100	150	mA
Transmitter	Minimum	Typical	Maximum	Unit
Power Levels	14.5	17	19.5	dBm
Spectrum Mask				
• 1st side lobes			-30	dBr
• 2nd side lobes			-50	dBr
Power-on/off ramp			2.0	μs
RF Carrier Suppression	15			dB
Modulation Accuracy			35	%
Frequency Tolerance	-20		20	ppm
Spurious Emissions (BW = 100 kHz)				
• 30 Hz ≤ f < 1000 MHz			-36	dBm
• 1000 MHz ≤ f < 12750 MHz			-30	dBm
• 1800 MHz < f ≤ 1900 MHz			-47	dBm
• 5150 MHz < f ≤ 5300 MHz			-47	dBm
Receiver	Minimum	Typical	Maximum	Unit
Minimum Input Level (FER ≤ 8%)			-76	dBm
Maximum Input Level (FER ≤ 8%)	-10			dBm
Adjacent Channel Rejection (FER ≤ 8%)	35			dB

13.2 DC/RF Characteristics for IEEE 802.11g - 2.4 GHz

Conditions: 25 °C, VBAT = 3.3V, VDDIO = 3.3V, 54 Mbps mode unless otherwise specified.

Table 19: DC/RF Characteristics for IEEE 802.11g - 2.4 GHz

Items	Contents			
Specification	IEEE 802.11g - 2.4 GHz			
Mode	OFDM			
Channel Frequency	2412 to 2472 MHz (5 MHz)			
Data Rate	6, 9, 12, 18, 24, 36, 48, 54 Mbps			
Current Consumption	Minimum	Typical	Maximum	Unit
• Tx mode		330	430	mA
• Rx mode		100	150	mA
Transmitter	Minimum	Typical	Maximum	Unit
Power Levels	12.5	15	17.5	dBm
Spectrum Mask				
• at $f_c \pm 11$ MHz			-20	dBr
• at $f_c \pm 20$ MHz			-28	dBr
• at $f_c \geq \pm 30$ MHz			-40	dBr
Constellation Error			-25	dB
Frequency Tolerance	-20		20	ppm
Spurious Emissions (BW = 100 kHz)				
• $30 \text{ Hz} \leq f < 1000 \text{ MHz}$			-36	dBm
• $1000 \text{ MHz} \leq f < 12750 \text{ MHz}$			-30	dBm
• $1800 \text{ MHz} < f \leq 1900 \text{ MHz}$			-47	dBm
• $5150 \text{ MHz} < f \leq 5300 \text{ MHz}$			-47	dBm
Receiver	Minimum	Typical	Maximum	Unit
Minimum Input Level (PER \leq 10%)			-65	dBm
Maximum Input Level (PER \leq 10%)	-20			dBm
Adjacent Channel Rejection (PER \leq 10%)	-1			dB

13.3 DC/RF Characteristics for IEEE 802.11n - 2.4 GHz

Conditions: 25 °C, VBAT = 3.3V, 65 Mbps (MCS7 – HT 20 MHz) mode unless otherwise specified.

Table 20: DC/RF Characteristics for IEEE 802.11n - 2.4 GHz

Items	Contents			
Specification	IEEE 802.11n - 2.4 GHz			
Mode	OFDM			
Channel Frequency	2412 to 2472 MHz (5 MHz)			
Data Rate	6.5, 13, 19.5, 26, 39, 52, 58.5, 65 Mbps			
Current Consumption	Minimum	Typical	Maximum	Unit
• Tx mode		330	430	mA
• Rx mode		100	150	mA
Transmitter	Minimum	Typical	Maximum	Unit
Power Levels	12.5	15	17.5	dBm
Spectrum Mask				
• at $f_c \pm 11$ MHz			-20	dBr
• at $f_c \pm 20$ MHz			-28	dBr
• at $f_c \geq \pm 30$ MHz			-45	dBr
Constellation Error (Measured at enhanced mode)			-27	dB
Frequency Tolerance	-20		20	ppm
Spurious Emissions (BW = 100 kHz)				
• $30 \text{ Hz} \leq f < 1000 \text{ MHz}$			-36	dBm
• $1000 \text{ MHz} \leq f < 12750 \text{ MHz}$			-30	dBm
• $1800 \text{ MHz} < f \leq 1900 \text{ MHz}$			-47	dBm
• $5150 \text{ MHz} < f \leq 5300 \text{ MHz}$			-47	dBm
Receiver	Minimum	Typical	Maximum	Unit
Minimum Input Level (PER \leq 10%)			-64	dBm
Maximum Input Level (PER \leq 10%)	-20			dBm
Adjacent Channel Rejection (PER \leq 10%)	-2			dB

13.4 DC/RF Characteristics for IEEE 802.11a - 5 GHz

Conditions: 25 °C, VBAT = 3.3V, 54 Mbps mode unless otherwise specified.

Table 21: DC/RF Characteristics for IEEE 802.11a - 5 GHz

Items	Contents			
Specification	IEEE 802.11a - 5 GHz			
Mode	OFDM			
Channel Frequency	5180 to 5825 MHz			
Data Rate	6, 9, 12, 18, 24, 36, 48, 54 Mbps			
Current Consumption	Minimum	Typical	Maximum	Unit
• Tx mode		400	500	mA
• Rx mode		120	170	mA
Transmitter	Minimum	Typical	Maximum	Unit
Power Levels	11.5	14	16.5	dBm
Spectrum Mask				
• at fc +/- 11 MHz			-20	dBr
• at fc +/- 20 MHz			-28	dBr
• at fc ≥ +/- 30 MHz			-40	dBr
Constellation Error			-25	dB
Frequency Tolerance	-20		20	ppm
Spurious Emissions (BW = 100 kHz)				
• 30 Hz ≤ f < 1000 MHz			-36	dBm
• 1000 MHz ≤ f < 26000 MHz			-30	dBm
Receiver	Minimum	Typical	Maximum	Unit
Minimum Input Level (PER ≤ 10%)			-65	dBm
Maximum Input Level (PER ≤ 10%)	-30			dBm
Adjacent Channel Rejection (PER < 10%)	-1			dB

13.5 DC/RF Characteristics for IEEE 802.11n (HT20) - 5 GHz

Conditions: 25 °C, VBAT = 3.3V, 65 Mbps (MCS7 - HT 20 MHz) mode unless otherwise specified.

Table 22: DC/RF Characteristics for IEEE 802.11n (HT20) - 5 GHz

Items	Contents			
Specification	IEEE 802.11n - 5 GHz			
Mode	OFDM			
Channel Frequency	5180 to 5825 MHz			
Data Rate	6.5, 13, 19.5, 26, 39, 52, 58.5, 65 Mbps			
Current Consumption	Minimum	Typical	Maximum	Unit
• Tx mode		380	480	mA
• Rx mode		120	170	mA
Transmitter	Minimum	Typical	Maximum	Unit
Power Levels	10.5	13	15.5	dBm
Spectrum Mask				
• at fc +/- 11 MHz			-20	dBr
• at fc +/- 20 MHz			-28	dBr
• at fc ≥ +/- 30 MHz			-40	dBr
Constellation Error (Measured at enhanced mode)			-27	dB
Frequency tolerance	-20		20	ppm
Spurious Emissions (BW = 100 kHz)				
• 30 Hz ≤ f < 1000 MHz			-36	dBm
• 1000 MHz ≤ f < 26000 MHz			-30	dBm
Receiver	Minimum	Typical	Maximum	Unit
Minimum Input Level (PER ≤ 10%)			-64	dBm
Maximum Input Level (PER ≤ 10%)	-30			dBm
Adjacent Channel Rejection (PER < 10%)	16			dB

13.6 DC/RF Characteristics for IEEE 802.11n (HT40) - 5 GHz

Conditions: 25 °C, VBAT = 3.3V, 135 Mbps (MCS7 - HT 40 MHz) mode unless otherwise specified.

Table 23: DC/RF Characteristics for IEEE 802.11n (HT40) - 5 GHz

Items	Contents			
Specification	IEEE 802.11n - 5 GHz			
Mode	OFDM			
Channel Frequency	5180 to 5825 MHz			
Data Rate	13.5,27,40.5,54,81,108,121.5,135 Mbps			
Current Consumption	Minimum	Typical	Maximum	Unit
• Tx mode		410	510	mA
• Rx mode		140	190	mA
Transmitter	Minimum	Typical	Maximum	Unit
Power Levels	9.5	12	14.5	dBm
Spectrum Mask				
• at fc +/- 21 MHz			-20	dBr
• at fc +/- 40 MHz			-28	dBr
• at fc ≥ +/- 60 MHz			-40	dBr
Constellation Error (Measured at enhanced mode)			-27	dB
Frequency tolerance	-20		20	ppm
Spurious Emissions (BW = 100 kHz)				
• 30 Hz ≤ f < 1000 MHz			-36	dBm
• 1000 MHz ≤ f < 26000 MHz			-30	dBm
Receiver	Minimum	Typical	Maximum	Unit
Minimum Input Level (PER ≤ 10%)			-61	dBm
Maximum Input Level (PER ≤ 10%)	-30			dBm
Adjacent Channel Rejection (PER < 10%)	-2			dB

13.7 DC/RF Characteristics for IEEE 802.11ac (HT40) - 5 GHz

Conditions: 25 °C, VBAT = 3.3V, 180 Mbps (MCS9 - HT 40 MHz) mode unless otherwise specified.

Table 24: DC/RF Characteristics for IEEE 802.11ac (HT40) - 5 GHz

Items	Contents			
Specification	IEEE 802.11ac - 5 GHz			
Mode	OFDM			
Channel Frequency	5190 to 5795 MHz			
Data Rate	13.5,27,40.5,54,81,108,121.5,135,162,180 Mbps			
Current Consumption	Minimum	Typical	Maximum	Unit
• Tx mode		420	520	mA
• Rx mode		140	200	mA
Transmitter	Minimum	Typical	Maximum	Unit
Power Levels	7.5	10	12.5	dBm
Spectrum Mask				
• at fc +/- 21 MHz			-20	dBr
• at fc +/- 40 MHz			-28	dBr
• at fc ≥ +/- 60 MHz			-40	dBr
Constellation Error (Measured at enhanced mode)			-32	dB
Frequency Tolerance	-20		20	ppm
Spurious Emissions (BW = 100 kHz)				
• 30 Hz ≤ f < 1000 MHz			-36	dBm
• 1000 MHz ≤ f < 26000 MHz			-30	dBm
Receiver	Minimum	Typical	Maximum	Unit
Minimum Input Level (PER ≤ 10%)			-54	dBm
Maximum Input Level (PER ≤ 10%)	-30			dBm

13.8 DC/RF Characteristics for IEEE 802.11ac (HT80) - 5 GHz

Conditions: 25 °C, VBAT = 3.3V, 390 Mbps (MCS9 - HT 80 MHz) mode unless otherwise specified.

Table 25: DC/RF Characteristics for IEEE 802.11ac (HT80) - 5 GHz

Items	Contents			
Specification	IEEE 802.11ac - 5 GHz			
Mode	OFDM			
Channel Frequency	5210 to 5775 MHz			
Data Rate	29.3,58.5,87.8,117,175.5,234,263.3,292.5,351,390 Mbps			
Current Consumption	Minimum	Typical	Maximum	Unit
• Tx mode		440	540	mA
• Rx mode		180	250	mA
Transmitter	Minimum	Typical	Maximum	Unit
Power Levels	7.5	10	12.5	dBm
Spectrum Mask				
• at fc +/- 41 MHz			-20	dBr
• at fc +/- 80 MHz			-28	dBr
• at fc ≥ +/- 120 MHz			-40	dBr
Constellation Error (Measured at enhanced mode)			-32	dB
Spurious Emissions (BW = 100 kHz)				
• 30 Hz ≤ f < 1000 MHz			-36	dBm
• 1000 MHz ≤ f < 26000 MHz			-30	dBm
Receiver	Minimum	Typical	Maximum	Unit
Minimum Input Level (PER ≤ 10%)			-51	dBm
Maximum Input Level (PER ≤ 10%)	-30			dBm
Adjacent Channel Rejection (PER < 10%)	-9			dB

13.9 DC/RF Characteristics for Bluetooth

Conditions: 25 °C, VBAT = 3.3V

Table 26: DC/RF Characteristics for Bluetooth

Items	Contents			
Bluetooth Specification (power class)	Version 5.2 (Class 2)			
Channel Frequency (spacing)	2402 to 2480 MHz (1 MHz)			
Current Consumption	Minimum	Typical	Maximum	Unit
• DH5 Packet 50% Rx/Tx Slot Duty Cycle		50	65	mA
• 2DH5 Packet 50% Rx/Tx Slot Duty Cycle		40	55	mA
• 3DH5 Packet 50% Rx/Tx Slot Duty Cycle		40	45	mA
Transmitter	Minimum	Typical	Maximum	Unit
Output Power@DH5	7.5	11	14.5	dBm
Frequency Range	2400		2483.5	MHz
20 dB bandwidth			1	MHz
Adjacent Channel Power ²				
• [M-N] = 2			-20	dBm
• [M-N] ≥ 3			-40	dBm
Modulation Characteristics				
• Modulation $\Delta f_{1\text{avg}}$	140		175	kHz
• Modulation $\Delta f_{2\text{max}}$	115			kHz
• Modulation $\Delta f_{2\text{avg}} / \Delta f_{1\text{avg}}$	0.8			
Carrier Frequency Drift				
• 1slot	-25		+25	kHz
• 3slot / 5slot	-40		+40	kHz
• Maximum Drift Rate	-20		+20	kHz/50 μ s
EDR Relative Power	-4		+1	dB
EDR Carrier Frequency Stability and Modulation Accuracy				
• ω_i	-75		+75	kHz
• $\omega_i + \omega_o$	-75		+75	kHz
• ω_o	-10		+10	kHz
• RMS DEVM (DQPSK)			20	%
• Peak DEVM (DQPSK)			35	%
• 99% DEVM (DQPSK)			30	%
• RMS DEVM (8DPSK)			13	%
• Peak DEVM (8DPSK)			25	%
• 99% DEVM (8DPSK)			20	%
Spurious Emissions (BW = 100 kHz)				
• 30 Hz ≤ f < 1000 MHz			-36	dBm
• 1000 MHz ≤ f < 12750 MHz			-30	dBm
• 1800 MHz < f ≤ 1900 MHz			-47	dBm
• 5150 MHz < f ≤ 5300 MHz			-47	dBm
Receiver	Minimum	Typical	Maximum	Unit
Sensitivity (BER ≤ 0.1%)			-80	dBm
Maximum Input Level (BER ≤ 0.1%)	-20			dBm
EDR Sensitivity (BER ≤ 0.007%)				
• 8DPSK			-70	dBm

² Up to three spurious responses within Bluetooth limits are allowed.

13.10 DC/RF Characteristics for Bluetooth Low Energy

Conditions: 25 °C, VBAT = 3.3V

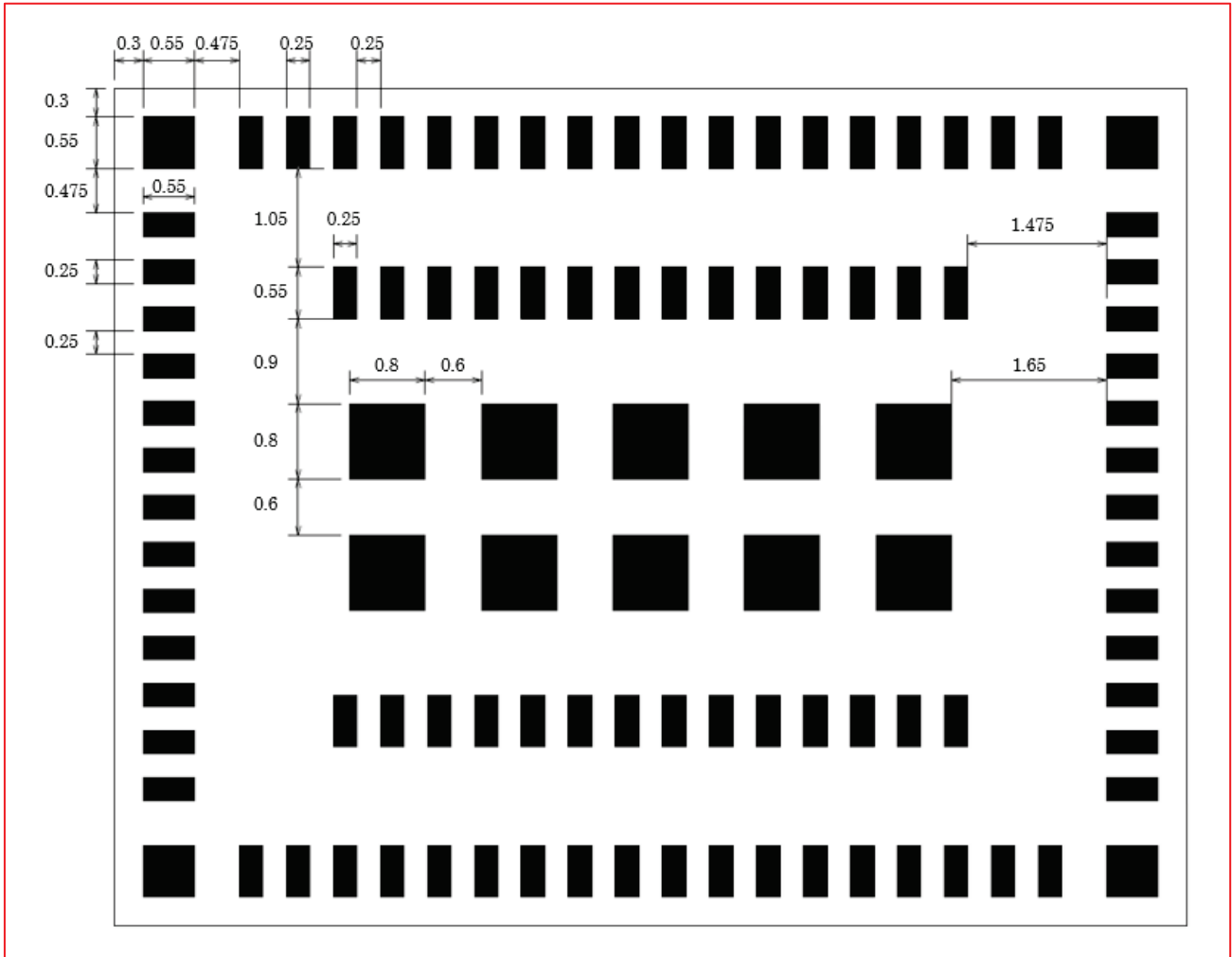
Table 27: DC/RF Characteristics for BLE

Items	Contents			
Bluetooth Specification (power class)	Version 5.2(LE)			
Channel Frequency (spacing)	2402 to 2480 MHz (2 MHz)			
Number of RF Channel	40			
Current Consumption	Minimum	Typical	Maximum	Unit
• Tx mode		30	45	mA
• Rx mode		15	25	mA
Item / Condition	Minimum	Typical	Maximum	Unit
Center Frequency	2402		2480	MHz
Channel Spacing		2		MHz
Number of RF channel		40		
Output Power	0	3	7.5	dBm
Modulation Characteristics				
• $\Delta f_{1\text{avg}}$	225		275	kHz
• $\Delta f_{2\text{max}}$ (at 99.9%)	185			kHz
• $\Delta f_{2\text{avg}} / \Delta f_{1\text{avg}}$	0.8			
Carrier Frequency Offset and Drift				
• Frequency Offset			150	kHz
• Frequency Drift			50	kHz
• Drift Rate			20	kHz
Receiver Sensitivity (PER < 30.8%)			-70	dBm
Maximum Input Signal Level (PER < 30.8%)	-10			dBm
PER Report Integrity (-30 dBm input)	50		65.4	%

14 Land Pattern

The land pattern diagram for Type 1XA module is shown in **Figure 20**.

Figure 20: Land Pattern (Unit: mm)



15 Radio Regulatory Certification by Country for LBEE5XV1XA

This section includes regulatory certification information / user guide of the following regions:

- Japan
- FCC
- ISED
- Europe

15.1 Japan

- Application Model Name: LBEE5XV1XA
- Certification Number: 007-AJ0192



This module is a product that has been authorized construction design certification based on the following certificate of construction type.



- In the 5 GHz frequency band, three types of 5.2 GHz / 5.3 GHz / 5.6 GHz bands (W52 / W53 / W56) can be used.
- Outdoor use of the 5.2 GHz / 5.3 GHz band wireless LAN (W52 / W53) is prohibited by the Certificate of Construction Type.
- W53 / W56 for STA function only.

The end product or user manual is recommended to describe all the contents shown below.



- This product has built-in specified radio equipment which received construction design certification (certification number: 007-AJ0192) based on the Certificate of Construction.
- The W52 / W53 in the 5 GHz band is prohibited from outdoor use under the Japanese Certificate of Construction Type.

Table 28, Table 29 and **Table 30** show the IC SISO, MIMO, simultaneous transmission per antenna port power table for 2.4 GHz for WLAN and Bluetooth. **Table 31** shows the IC SISO simultaneous transmission per antenna port power table for 5 GHz WLAN.

Table 32 shows the IC MIMO simultaneous transmission per antenna port power table for 5 GHz WLAN.

Table 28: Japan Power Level 2.4 GHz WLAN Per Antenna Port (SISO/1SS)

Mode	Rate	Maximum Tune Up Tolerance (dBm)
Channels		1 ~ 13
IEEE 802.11b	All Rates	13.5 ± 2.5
IEEE 802.11g	6 Mbps, 9 Mbps, 12 Mbps, 18 Mbps	15.5 ± 2.5
	24 Mbps, 36 Mbps, 48 Mbps, 54 Mbps	15.0 ± 2.5
IEEE 802.11n (HT20)	MCS0, MCS1, MCS2, MCS3	15.5 ± 2.5
	MCS4, MCS5, MCS6, MCS7	15.0 ± 2.5
Equivalent to IEEE 802.11ac (VHT20)	MCS0, MCS1, MCS2, MCS3	15.5 ± 2.5
	MCS4, MCS5, MCS6, MCS7	15.0 ± 2.5
	MCS8	14.0 ± 2.5

Table 29: Japan Power Level 2.4 GHz WLAN Per Antenna Port (MIMO/2SS)

Mode	Rate	Maximum Tune Up Tolerance (dBm)
Channels		1 ~ 13
IEEE 802.11n (HT20)	MCS8, MCS9, MCS10, MCS11, MCS12, MCS13, MCS14, MCS15	12.5 ± 2.5
Equivalent to IEEE 802.11ac (VHT20)	MCS0, MCS1, MCS2, MCS3, MCS4, MCS5, MCS6, MCS7, MCS8	12.5 ± 2.5

Table 30: Japan Power Level 2.4 GHz BT/BLE Per Antenna Port

Frequency [MHz]	Typical Output Power Level (dBm)		
	DH5	3DH5	BLE
2402	11	7	3
2440	11	7	3
2480	11	7	3



The Japan Bluetooth power table (**Table 30**) is valid for FCC, ISED, and Europe.

Table 31: Japan Power Level 5 GHz WLAN Per Antenna Port (SISO/1SS)

Mode	Channel	Rate	Maximum Tune Up Tolerance (dBm)
IEEE 802.11a	36 ~ 48	6 Mbps, 9 Mbps, 12 Mbps, 18 Mbps, 24 Mbps	12.5 ± 2.5
		36 Mbps, 48 Mbps, 54 Mbps	12.5 ± 2.5
	52 ~ 64	6 Mbps, 9 Mbps, 12 Mbps, 18 Mbps, 24 Mbps	12.5 ± 2.5
		36 Mbps, 48 Mbps, 54 Mbps	12.5 ± 2.5
	100 ~ 144	6 Mbps, 9 Mbps, 12 Mbps, 18 Mbps, 24 Mbps	15.0 ± 2.5
		36 Mbps, 48 Mbps, 54 Mbps	14.0 ± 2.5
IEEE 802.11n/ac (HT20)	36 ~ 48	MCS0 ~ MCS3	12.5 ± 2.5
		MCS4 ~ MCS6	12.5 ± 2.5
		MCS7	12.5 ± 2.5
	52 ~ 64	MCS0 ~ MCS3	12.75 ± 2.5
		MCS4 ~ MCS6	12.75 ± 2.5
		MCS7	12.75 ± 2.5
	100 ~ 144	MCS0 ~ MCS3	15.0 ± 2.5
		MCS4 ~ MCS6	14.0 ± 2.5
		MCS7	13.0 ± 2.5
IEEE 802.11n/ac (HT40)	38 ~ 46	MCS0 ~ MCS5	13.25 ± 2.5
		MCS6	13.0 ± 2.5
		MCS7	12.0 ± 2.5
	54 ~ 62	MCS0 ~ MCS5	13.5 ± 2.5
		MCS6	13.0 ± 2.5
		MCS7	12.0 ± 2.5
	102 ~ 142	MCS0 ~ MCS5	14.0 ± 2.5
		MCS6	13.0 ± 2.5
		MCS7	12.0 ± 2.5
IEEE 802.11ac (VHT20)	36 ~ 48	MCS8	12.0 ± 2.5
	52 ~ 64	MCS8	12.0 ± 2.5
	100 ~ 144	MCS8	12.0 ± 2.5
IEEE 802.11ac (VHT40)	38 ~ 46	MCS8	11.0 ± 2.5
		MCS9	10.0 ± 2.5
	54 ~ 62	MCS8	11.0 ± 2.5
		MCS9	10.0 ± 2.5
	102 ~ 142	MCS8	11.0 ± 2.5
		MCS9	10.0 ± 2.5
IEEE 802.11ac (VHT80)	42	MCS0 ~ MCS5	13.0 ± 2.5
		MCS6	13.0 ± 2.5
		MCS7	12.0 ± 2.5
		MCS8	11.0 ± 2.5
		MCS9	10.0 ± 2.5
	58	MCS0 ~ MCS5	13.0 ± 2.5
		MCS6	13.0 ± 2.5
		MCS7	12.0 ± 2.5
		MCS8	11.0 ± 2.5
		MCS9	10.0 ± 2.5
	106 ~ 138	MCS0 ~ MCS5	14.0 ± 2.5
		MCS6	13.0 ± 2.5
		MCS7	12.0 ± 2.5
		MCS8	11.0 ± 2.5
		MCS9	10.0 ± 2.5

Table 32: Japan Power Level 5 GHz WLAN Per Antenna Port (MIMO/2SS)

Mode	Channel	Rate	Maximum Tune Up Tolerance (dBm)
IEEE 802.11n (HT20)	36 ~ 48	MCS8 ~ MCS15	11.0 ± 2.5
IEEE 802.11n/ac (HT40)	38 ~ 46	MCS8 ~ MCS15	11.0 ± 2.5
IEEE 802.11ac (VHT20)	36 ~ 48	MCS0 ~ MCS8	11.0 ± 2.5
IEEE 802.11ac (VHT40)	38 ~ 46	MCS0 ~ MCS8	11.0 ± 2.5
		MCS9	10.0 ± 2.5
IEEE 802.11ac (VHT80)	42	MCS0 ~ MCS8	11.0 ± 2.5
		MCS9	10.0 ± 2.5

15.2 FCC

- Model Name: LBEE5XV1XA, LBEE5XV2BA, LBEE5XV1ZA
- FCC ID: VPYLBEE5XV1XA

Since this module is not sold to general end users directly, there is no user manual for this module. Therefore, for the details about this module, please refer to the specification sheet of module.



1. This module should be installed in the host device according to the interface specification (installation procedure).
2. The OEM integrator has to be aware not to provide information to the end user regarding how to install or remove this RF module in the end user's manual of the end product which integrates this module.

The end user manual shall include all required regulatory information/warning as shown in user manual.

15.2.1 Information to Display on Host Device and User Manual

15.2.1.1 Information on Host Device

The following information must be indicated on the host device of this module:

- Contains Transmitter Module FCC ID: VPYLBEE5XV1XA or Contains FCC ID: VPYLBEE5XV1XA



This device complies with part 15 of the FCC Rules. Operation is subject to the following two conditions:

- This device may not cause harmful interference.
- This device must accept any interference received, including interference that may cause undesired operation.



If it is difficult to describe this statement on the host device due to the size, please describe in the user's manual and also either describe on the device packaging or on a removable label attached to the device.

15.2.1.2 Information in User Manual

The following statements must be described on the user manual of the host device of this module:

- **FCC CAUTION:** Changes or modifications not expressly approved by the party responsible for compliance could void the user's authority to operate the equipment.

- This transmitter must not be co-located or operated in conjunction with any other antenna or transmitter.

15.2.2 Equipment Installation for FCC

There are two types of installation for host device.

15.2.2.1 Portable Equipment

Equipment for which the spaces between human body and antenna are used within 20 cm. When installing it in portable equipment, please describe the following information to the manual.



It is necessary to take a SAR test with your set mounting this module. Class II permissive change application is necessary using the SAR report. Please contact Murata.

15.2.2.2 Mobile Equipment

Equipment used at a position in which the spaces between human body and antenna exceeded 20 cm. When installing it in mobile equipment, please describe the following information to the manual.



This equipment complies with FCC radiation exposure limits set forth for an uncontrolled environment and meets the FCC radio frequency (RF) Exposure Guidelines. This equipment should be installed and operated keeping the radiator at least 20 cm or more away from person's body.

15.2.3 Compliance with FCC requirement 15.407(c)

Data transmission is always initiated by software, which is the passed down through the MAC, through the digital and analog baseband, and finally to the RF chip. Several special packets are initiated by the MAC. These are the only ways the digital baseband portion will turn on the RF transmitter, which it then turns off at the end of the packet. Therefore, the transmitter will be on only while one of the aforementioned packets is being transmitted. In other words, this device automatically discontinues transmission in case of either absence of information to transmit or operational failure.



Frequency Tolerance: ± 20 ppm

15.2.4 Power Level for FCC

Table 33 and **Table 34** show the IC SISO and MIMO, simultaneous transmission per antenna port power table for 2.4 GHz for WLAN. **Table 35**, **Table 36**, and **Table 37** show the IC SISO simultaneous transmission per antenna port power table for 5 GHz WLAN.

Table 38, **Table 39**, and **Table 40** show the IC MIMO simultaneous transmission per antenna port power table for 5 GHz WLAN.

Table 33: FCC Power Level 2.4 GHz WLAN Per Antenna Port (SISO/1SS)

Mode	Rate	Typical Output Power Level (dBm)										
		1	2	3	4	5	6	7	8	9	10	11
Channels												
IEEE 802.11b	All Rates	14.5	15.0	17.0	17.0	17.0	17.0	17.0	17.0	17.0	15.0	15.5
IEEE 802.11g	All Rates	12.5	14.0	14.0	14.5	14.5	15.5	16.5	15.5	15.0	14.0	12.5
IEEE 802.11n (HT20)	MCS0 ~ MCS7	11.0	13.0	14.0	14.0	14.5	15.5	15.5	15.0	14.5	12.5	11.5
Equivalent to IEEE 802.11ac (VHT20)	MCS0 ~ MCS7	11.0	13.0	14.0	14.0	14.5	15.5	15.5	15.0	14.5	12.5	11.5
	MCS8	11.0	13.0	14.0	14.0	14.0	14.0	14.0	14.0	14.0	12.5	11.5

Table 34: FCC Power Level 2.4 GHz WLAN Per Antenna Port (MIMO/2SS)

Mode	Rate	Typical Output Power Level (dBm)										
		1	2	3	4	5	6	7	8	9	10	11
Channels												
IEEE 802.11n (HT20)	MCS8 ~ MCS15	8.0	11.0	11.5	13.0	13.0	14.0	14.0	13.0	12.0	10.5	10.0
Equivalent to IEEE 802.11ac (VHT20)	MCS0 ~ MCS8	8.0	11.0	11.5	13.0	13.0	14.0	14.0	13.0	12.0	10.5	10.0

Table 35: FCC Power Level 5 GHz WLAN Per Antenna Port (SISO/1SS) (W52-53)

Mode	Rate	Typical Output Power Level (dBm)						
		36	40	44 ~ 48	52 ~ 56	60	64	
11a	6 ~ 24 Mbps	10.0	13.5	13.5	15.0	15.0	10.5	
	36 ~ 54 Mbps	10.0	13.5	13.5	14.0	14.0	10.5	
11n HT20	MCS0 ~ MCS3	9.0	13.5	13.5	15.0	15.0	10.0	
	MCS4 ~ MCS6	9.0	13.5	13.5	14.0	14.0	10.0	
	MCS7	9.0	13.5	13.0	13.0	13.0	10.0	
11ac VHT20	MCS0 ~ MCS3	9.0	13.5	13.5	15.0	15.0	10.0	
	MCS4 ~ MCS6	9.0	13.5	13.5	14.0	14.0	10.0	
	MCS7	9.0	13.0	13.0	13.0	13.0	10.0	
	MCS8	9.0	12.0	12.0	12.0	12.0	10.0	
Channels		38	46	54	62			
11n/ac HT40	MCS0 ~ MCS5	10.5	13.0	14.0	9.5			
	MCS6	10.5	13.0	13.0	9.5			
	MCS7	10.5	12.0	12.0	9.5			
11ac VHT40	MCS8	10.5	11.0	11.0	9.5			
	MCS9	10.5	10.0	10.0	9.5			
Channels		42	58					
11ac VHT80	MCS0 ~ MCS9	8.0		5.5				

Table 36: FCC Power Level 5 GHz WLAN Per Antenna Port (SISO/1SS) (W56)

Mode	Rate	Typical Output Power Level (dBm)						
Channels		100	104	108~112	116~128	132~136	140	144
11a	6 ~ 24 Mbps	10.0	15.0	15.0	15.0	15.0	10.0	15.0
	36 ~ 54 Mbps	10.0	14.0	14.0	14.0	14.0	10.0	14.0
11n/ac HT20	MCS0 ~ MCS3	9.0	15.0	15.0	15.0	15.0	9.0	15.0
	MCS4 ~ MCS6	9.0	14.0	14.0	14.0	14.0	9.0	14.0
	MCS7	9.0	13.0	13.0	13.0	13.0	9.0	13.0
11ac VHT20	MCS8	9.0	12.0	12.0	12.0	12.0	9.0	12.0
Channels		102	110	118~126	134	142		
11n/ac HT40	MCS0 ~ MCS5	8.5	14.0	14.0	12.0	14.0		
	MCS6	8.5	13.0	13.0	12.0	13.0		
	MCS7	8.5	12.0	12.0	12.0	12.0		
11ac VHT40	MCS8	8.5	11.0	11.0	11.0	11.0		
	MCS9	8.5	10.0	10.0	10.0	10.0		
Channels		106	122	138				
11ac VHT80	MCS0 ~ MCS5	7.5	14.0	14.0				
	MCS6	7.5	13.0	13.0				
	MCS7	7.5	12.0	12.0				
	MCS8	7.5	11.0	11.0				
	MCS9	7.5	10.0	10.0				

Table 37: FCC Power Level 5 GHz WLAN Per Antenna Port (SISO/1SS) (W58)

Mode	Rate	Typical Output Power Level (dBm)	
Channels		149 ~ 161	165
11a	6 ~ 24 Mbps	15.0	15.0
	36 ~ 54 Mbps	14.0	14.0
11n/ac HT20	MCS0 ~ MCS3	15.0	15.0
	MCS4 ~ MCS6	14.0	14.0
	MCS7	13.0	13.0
11ac VHT20	MCS8	12.0	12.0
Channels		151 ~ 159	
11n/ac HT40	MCS0 ~ MCS5	14.0	
	MCS6	13.0	
	MCS7	12.0	
11ac VHT40	MCS8	11.0	
	MCS9	10.0	
Channels		155	
11ac VHT80	MCS0 ~ MCS6	13.0	
	MCS7	12.0	
	MCS8	11.0	
	MCS9	10.0	

Table 38: FCC Power Level 5 GHz WLAN Per Antenna Port (MIMO/2SS) (W52-53)

Mode	Rate	Typical Output Power Level (dBm)					
Channels		36	40	44 ~ 48	52 ~ 56	60	64
11n HT20	MCS8 ~ MCS14	7.5	10.5	10.5	14.0	14.0	7.0
	MCS15	7.5	10.5	10.5	13.0	13.0	7.0
11ac VHT20	MCS0 ~ MCS6	7.5	10.5	10.5	14.0	14.0	7.0
	MCS7	7.5	10.5	10.5	13.0	13.0	7.0
	MCS8	7.5	10.5	10.5	12.0	12.0	7.0
Channels		38	46	54	62		
11n/ac HT40	MCS8 ~ MCS13	7.5	10.0	14.0	7.0		
	MCS14	7.5	10.0	13.0	7.0		
	MCS15	7.5	10.0	12.0	7.0		
11ac VHT40	MCS0 ~ MCS5	7.5	10.0	14.0	7.0		
	MCS6	7.5	10.0	13.0	7.0		
	MCS7	7.5	10.0	12.0	7.0		
	MCS8	7.5	10.0	11.0	7.0		
	MCS9	7.5	10.0	10.0	7.0		
Channels		42	58				
11ac VHT80	MCS0 ~ MCS9	6.0		4.0			

Table 39: FCC Power Level 5 GHz WLAN Per Antenna Port (MIMO/2SS) (W56)

Mode	Rate	Typical Output Power Level (dBm)						
Channels		100	104	108~112	116~128	132~136	140	144
11n HT20	MCS8 ~ MCS11	7.0	14.5	14.5	14.5	14.5	6.0	14.5
	MCS12 ~ MCS14	7.0	14.0	14.0	14.0	14.0	6.0	14.0
	MCS15	7.0	13.0	13.0	13.0	13.0	6.0	13.0
11ac VHT20	MCS0 ~ MCS3	7.0	14.5	14.5	14.5	14.5	6.0	14.5
	MCS4 ~ MCS6	7.0	14.0	14.0	14.0	14.0	6.0	14.0
	MCS7	7.0	13.0	13.0	13.0	13.0	6.0	13.0
	MCS8	7.0	12.0	12.0	12.0	12.0	6.0	12.0
Channels		102	110	118~126	134	142		
11n/ac HT40	MCS8 ~ MCS13	8.0	14.0	14.0	9.0	14.0		
	MCS14	8.0	13.0	13.0	9.0	13.0		
	MCS15	8.0	12.0	12.0	9.0	12.0		
11ac VHT40	MCS0 ~ MCS5	8.0	14.0	14.0	9.0	14.0		
	MCS6	8.0	13.0	13.0	9.0	13.0		
	MCS7	8.0	12.0	12.0	9.0	12.0		
	MCS8	8.0	11.0	11.0	9.0	11.0		
	MCS9	8.0	10.0	10.0	9.0	10.0		
Channels		106	122	138				
11ac VHT80	MCS0 ~ MCS5	5.5	14.0	14.0				
	MCS6	5.5	13.0	13.0				
	MCS7	5.5	12.0	12.0				

Mode	Rate	Typical Output Power Level (dBm)		
	MCS8	5.5	11.0	11.0
	MCS9	5.5	10.0	10.0


Table 40: FCC Power Level 5 GHz WLAN Per Antenna Port (MIMO/2SS) (W58)

Mode	Rate	Typical Output Power Level (dBm)	
Channels		149 ~ 161	165
11n HT20	MCS8 ~ MCS11	15.0	15.0
	MCS12 ~ MCS14	14.0	14.0
	MCS15	13.0	13.0
11ac VHT20	MCS0 ~ MCS3	15.0	15.0
	MCS4 ~ MCS6	14.0	14.0
	MCS7	13.0	13.0
	MCS8	12.0	12.0
Channels		151 ~ 159	
11n/ac HT40	MCS8 ~ MCS13	14.0	
	MCS14	13.0	
	MCS15	12.0	
11ac VHT40	MCS0 ~ MCS5	14.0	
	MCS6	13.0	
	MCS7	12.0	
	MCS8 ~ MCS13	14.0	
	MCS14	13.0	
Channels		155	
11ac VHT80	MCS0 ~ MCS9	10.5	

15.3 ISED

- Model Name: LBEE5XV1XA_3ANT and LBEE5XV1XA_2ANT
- IC Number: 772C-LBEE5XV1XA

This module is not sold to general end users directly, therefore, there is no user manual of module. For the details about this module, please refer to the specification sheet for the same.



1. This module should be installed in the host device according to the interface specification (installation procedure).
2. The OEM integrator has to be aware not to provide information to the end user regarding how to install or remove this RF module in the end user's manual of the end product which integrates this module.

The end user manual shall include all required regulatory information/warning as shown in User manual.

Table 41 shows the certified antenna list for type 1XA module.

Table 41: Certified Antenna List


No.	Maker	Support Antenna				
		P/N	Form Factor	Type	Gain (dBi)	
					2.4 GHz	5 GHz
1	Molex	146153	u.FL/flexible	dipole	3.2	4.25
2	Molex	146187	u.FL/flexible	dipole	3.4	4.75

15.3.1 Information to Display on Host Device and User Manual

15.3.1.1 Information on Host Device

The following information must be indicated on the host device of this module:

- Contains IC: 772C-LBEE5XV1XA
- In case of the final product which can be carried around to outdoor. The following indication is necessary to the final product.



When the STA function is used in channel 52, 54, 58.
 At the time of the channel 52 or 54 or 58 setting, please indicate "for indoor use only channel".
 During connecting, please show the channel number which connects.
 And please indicate that the end user may find out "for indoor use only channel".

- If the final product uses the following frequency, please note that there is a limit.

<p>English Version For indoor use only (5150 – 5250 MHz band)</p>
<p>French Version Pour usage intérieur seulement (5150 - 5250 MHz band)</p>

15.3.1.2 Information in User Manual

The following statements must be described on the user manual of the host device of this module:

<p>English Version</p> <p>This device complies with Industry Canada's applicable license-exempt RSSs. Operation is subject to the following two conditions:</p> <ul style="list-style-type: none"> • This device may not cause interference; and • This device must accept any interference, including interference that may cause undesired operation of the device.
<p>French Version</p> <p>Le présent appareil est conforme aux CNR d'Industrie Canada applicables aux appareils radio exempts de licence. L'exploitation est autorisée aux deux conditions suivantes:</p> <ul style="list-style-type: none"> • l'appareil ne doit pas produire de brouillage. • l'utilisateur de l'appareil doit accepter tout brouillage radioélectrique subi, même si le brouillage est susceptible d'en compromettre le fonctionnement.
<p>English Version</p> <p>Data transmission is always initiated by software, which is the passed down through the MAC, through the digital and analog baseband, and finally to the RF chip. Several special packets are initiated by the MAC. These are the only ways the digital baseband portion will turn on the RF transmitter, which it then turns off at the end of the packet. Therefore, the transmitter will be on only while one of the aforementioned packets is being transmitted. In other words, this device automatically discontinue transmission in case of either absence of information to transmit or operational failure.</p>
<p>French Version</p> <p>La transmission des données est toujours initiée par le logiciel, puis les données sont transmises par l'intermédiaire du MAC, par la bande de base numérique et analogique et, enfin, à la puce RF. Plusieurs paquets spéciaux sont initiés par le MAC. Ce sont les seuls moyens pour qu'une partie de la bande de base numérique active l'émetteur RF, puis désactive celui-ci à la fin du paquet. En conséquence, l'émetteur reste uniquement activé lors de la transmission d'un des paquets susmentionnés. En d'autres termes, ce dispositif interrompt automatiquement toute transmission en cas d'absence d'information à transmettre ou de défaillance.</p>

<p>English Version</p> <p>This radio transmitter (IC Number: 772C-LBEE5XV1XA) has been approved by Innovation, Science and Economic Development Canada to operate with the antenna types listed below, with the maximum permissible gain indicated. Antenna types not included in this list that have a gain greater than the maximum gain indicated for any type listed are strictly prohibited for use with this device.</p>
<p>French Version</p> <p>Le présent émetteur radio (IC Number: 772C-LBEE5XV1XA) a été approuvé par Innovation, Sciences et Développement économique Canada pour fonctionner avec les types d'antenne énumérés ci dessous et ayant un gain admissible maximal. Les types d'antenne non inclus dans cette liste, et dont le gain est supérieur au gain maximal indiqué pour</p>

15.3.2 Equipment Installation for ISED

There are two types of installation for host device.

15.3.2.1 Portable Equipment

Equipment for which the spaces between human body and antenna are used within 20 cm. When installing it in a portable equipment, please describe the following warning to the manual.



It is necessary to take a SAR test with your set mounting this module. Class IV permissive change application is necessary using the SAR report. Please contact Murata.

15.3.2.2 Mobile Equipment

Equipment used at position in which the spaces between human body and antenna exceeded 20 cm. When installing it in a mobile equipment, please describe the following information to the manual.

English Version

This equipment complies with IC radiation exposure limits set forth for an uncontrolled environment and meets RSS-102 of the IC radio frequency (RF) Exposure rules. This equipment should be installed and operated keeping the radiator at least 20 cm or more away from person's body.

French Version

Cet équipement est conforme aux limites d'exposition aux rayonnements énoncées pour un environnement non contrôlé et respecte les règles d'exposition aux fréquences radioélectriques (RF) CNR-102 de l'IC. Cet équipement doit être installé et utilisé en gardant une distance de 20 cm ou plus entre le radiateur et le corps humain.

15.3.3 Power Level for ISED

Table 42 and **Table 43** show the IC SISO and MIMO simultaneous transmission per antenna port power table for 2.4 GHz for WLAN. **Table 44**, **Table 45**, and **Table 46** show the IC SISO simultaneous transmission per antenna port power table for 5 GHz WLAN.

Table 47, **Table 48**, and **Table 49** show the IC MIMO simultaneous transmission per antenna port power table for 5 GHz WLAN.

Table 42: ISED Power Level 2.4 GHz WLAN Per Antenna Port (SISO/1SS)

Mode	Rate	Typical Output Power Level (dBm)										
		1	2	3	4	5	6	7	8	9	10	11
Channels												
IEEE 802.11b	All Rates	14.5	15.0	17.0	17.0	17.0	17.0	17.0	17.0	17.0	15.0	15.5
IEEE 802.11g	All Rates	12.5	14.0	14.0	14.5	14.5	15.5	16.5	15.5	15.0	14.0	12.5
IEEE 802.11n (HT20)	MCS0 ~ MCS3	11.0	13.0	14.0	14.0	14.5	15.5	15.5	15.0	14.5	12.5	11.5
	MCS4 ~ MCS7	11.0	13.0	14.0	14.0	14.5	15.0	15.0	15.0	14.5	12.5	11.5
Equivalent to IEEE 802.11ac (VHT20)	MCS0 ~ MCS3	11.0	13.0	14.0	14.0	14.5	15.5	15.5	15.0	14.5	12.5	11.5
	MCS4 ~ MCS7	11.0	13.0	14.0	14.0	14.5	15.0	15.0	15.0	14.5	12.5	11.5
	MCS8	11.0	13.0	14.0	14.0	14.0	14.0	14.0	14.0	14.0	12.5	11.5

Table 43: ISED Power Level 2.4 GHz WLAN Per Antenna Port (MIMO/2SS)

Mode	Rate	Typical Output Power Level (dBm)										
		1	2	3	4	5	6	7	8	9	10	11
Channels												
IEEE 802.11n (HT20)	MCS8 ~ MCS15	8.0	11.0	11.5	13.0	13.0	14.0	14.0	13.0	12.0	10.5	10.0
Equivalent to IEEE 802.11ac (VHT20)	MCS0 ~ MCS8	8.0	11.0	11.5	13.0	13.0	14.0	14.0	13.0	12.0	10.5	10.0

Table 44: ISED Power Level 5 GHz WLAN Per Antenna Port (SISO/1SS) (W52-53)

Mode	Rate	Typical Output Power Level (dBm)					
Channels		36	40	44 ~ 48	52 ~ 56	60	64
11a	6 ~ 24 Mbps	10.0	13.5	13.5	15.0	15.0	10.5
	36 ~ 54 Mbps	10.0	13.5	13.5	14.0	14.0	10.5
11n HT20	MCS0 ~ MCS3	9.0	13.5	13.5	15.0	15.0	10.0
	MCS4 ~ MCS6	9.0	13.5	13.5	14.0	14.0	10.0
	MCS7	9.0	13.5	13.0	13.0	13.0	10.0
11ac VHT20	MCS0 ~ MCS3	9.0	13.5	13.5	15.0	15.0	10.0
	MCS4 ~ MCS6	9.0	13.5	13.5	14.0	14.0	10.0
	MCS7	9.0	13.0	13.0	13.0	13.0	10.0
	MCS8	9.0	12.0	12.0	12.0	12.0	10.0
Channels		38	46	54	62		
11n/ac HT40	MCS0 ~ MCS5	10.5	13.0	14.0	9.5		
	MCS6	10.5	13.0	13.0	9.5		
	MCS7	10.5	12.0	12.0	9.5		
11ac VHT40	MCS8	10.5	11.0	11.0	9.5		
	MCS9	10.5	10.0	10.0	9.5		
Channels		42	58				
11ac VHT80	MCS0 ~ MCS9	8.0	5.5				

Table 45: ISED Power Level 5 GHz WLAN Per Antenna Port (SISO/1SS) (W56)

Mode	Rate	Typical Output Power Level (dBm)							
Channels		100	104	108~112	116	120~128	132~136	140	144
11a	6 ~ 24 Mbps	10.0	15.0	15.0	15.0		15.0	10.0	15.0
	36 ~ 54 Mbps	10.0	14.0	14.0	14.0		14.0	10.0	14.0
11n/ac HT20	MCS0 ~ MCS3	9.0	15.0	15.0	15.0		15.0	9.0	15.0
	MCS4 ~ MCS6	9.0	14.0	14.0	14.0		14.0	9.0	14.0
	MCS7	9.0	13.0	13.0	13.0		13.0	9.0	13.0
11ac VHT20	MCS8	9.0	12.0	12.0	12.0		12.0	9.0	12.0
Channels		102	110	118~126	134	142			
11n/ac HT40	MCS0 ~ MCS5	8.5	14.0		12.0	14.0			
	MCS6	8.5	13.0		12.0	13.0			
	MCS7	8.5	12.0		12.0	12.0			
11ac VHT40	MCS8	8.5	11.0		11.0	11.0			
	MCS9	8.5	10.0		10.0	10.0			
Channels		106	122	138					
11ac VHT80	MCS0 ~ MCS5	7.5		14.0					
	MCS6	7.5		13.0					
	MCS7	7.5		12.0					
	MCS8	7.5		11.0					
	MCS9	7.5		10.0					

Table 46: ISED Power Level 5 GHz WLAN Per Antenna Port (SISO/1SS) (W58)

Mode	Rate	Typical Output Power Level (dBm)	
Channels		149 ~ 161	165
11a	6 ~ 24 Mbps	15.0	15.0
	36 ~ 54 Mbps	14.0	14.0
11n/ac HT20	MCS0 ~ MCS3	15.0	15.0
	MCS4 ~ MCS6	14.0	14.0
	MCS7	13.0	13.0
11ac VHT20	MCS8	12.0	12.0
Channels		151 ~ 159	
11n/ac HT40	MCS0 ~ MCS5	14.0	
	MCS6	13.0	
	MCS7	12.0	
11ac VHT40	MCS8	11.0	
	MCS9	10.0	
Channels		155	
11ac VHT80	MCS0 ~ MCS6	13.0	
	MCS7	12.0	
	MCS8	11.0	
	MCS9	10.0	

Table 47: ISED Power Level 5 GHz WLAN Per Antenna Port (MIMO/2SS) (W52-53)

Mode	Rate	Typical Output Power Level (dBm)						
Channels		36	40	44	48	52 ~ 56	60	64
11n HT20	MCS8 ~ MCS14	7.5	6.0	10.5	5.5	14.0	14.0	7.0
	MCS15	7.5	6.0	10.5	5.5	13.0	13.0	7.0
11ac VHT20	MCS0 ~ MCS6	7.5	6.0	10.5	5.5	14.0	14.0	7.0
	MCS7	7.5	6.0	10.5	5.5	13.0	13.0	7.0
	MCS8	7.5	6.0	10.5	5.5	12.0	12.0	7.0
Channels		38		46		54		62
11n/ac HT40	MCS8 ~ MCS13	7.5		10.0		14.0		7.0
	MCS14	7.5		10.0		13.0		7.0
	MCS15	7.5		10.0		12.0		7.0
11ac VHT40	MCS0 ~ MCS5	7.5		10.0		14.0		7.0
	MCS6	7.5		10.0		13.0		7.0
	MCS7	7.5		10.0		12.0		7.0
	MCS8	7.5		10.0		11.0		7.0
	MCS9	7.5		10.0		10.0		7.0
Channels		42				58		
11ac VHT80	MCS0 ~ MCS9	6.0				4.0		

Table 48: ISED Power Level 5 GHz WLAN Per Antenna Port (MIMO/2SS) (W56)

Mode	Rate	Typical Output Power Level (dBm)							
Channels		100	104	108~112	116	120~128	132~136	140	144
11n HT20	MCS8 ~ MCS11	7.0	14.5	14.5	14.5		14.5	6.0	14.5
	MCS12 ~ MCS14	7.0	14.0	14.0	14.0		14.0	6.0	14.0
	MCS15	7.0	13.0	13.0	13.0		13.0	6.0	13.0
11ac VHT20	MCS0 ~ MCS3	7.0	14.5	14.5	14.5		14.5	6.0	14.5
	MCS4 ~ MCS6	7.0	14.0	14.0	14.0		14.0	6.0	14.0
	MCS7	7.0	13.0	13.0	13.0		13.0	6.0	13.0
	MCS8	7.0	12.0	12.0	12.0		12.0	6.0	12.0
Channels		102	110	118~126		134	142		
11n/ac HT40	MCS8 ~ MCS13	8.0	14.0			9.0	14.0		
	MCS14	8.0	13.0			9.0	13.0		
	MCS15	8.0	12.0			9.0	12.0		
11ac VHT40	MCS0 ~ MCS5	8.0	14.0			9.0	14.0		
	MCS6	8.0	13.0			9.0	13.0		
	MCS7	8.0	12.0			9.0	12.0		
	MCS8	8.0	11.0			9.0	11.0		
	MCS9	8.0	10.0			9.0	10.0		
Channels		106	122			138			
11ac VHT80	MCS0 ~ MCS5	5.5				14.0			
	MCS6	5.5				13.0			
	MCS7	5.5				12.0			
	MCS8	5.5				11.0			
	MCS9	5.5				10.0			

Table 49: ISED Power Level 5 GHz WLAN Per Antenna Port (MIMO/2SS) (W58)

Mode	Rate	Typical Output Power Level (dBm)	
Channels		149 ~ 161	165
11n HT20	MCS8 ~ MCS11	15.0	15.0
	MCS12 ~ MCS14	14.0	14.0
	MCS15	13.0	13.0
11ac VHT20	MCS0 ~ MCS3	15.0	15.0
	MCS4 ~ MCS6	14.0	14.0
	MCS7	13.0	13.0
	MCS8	12.0	12.0
Channels		151 ~ 159	
11n/ac HT40	MCS8 ~ MCS13	14.0	
	MCS14	13.0	
	MCS15	12.0	
11ac VHT40	MCS0 ~ MCS5	14.0	
	MCS6	13.0	
	MCS7	12.0	
	MCS8	11.0	

Mode	Rate	Typical Output Power Level (dBm)
	MCS9	10.0
Channels:		155
11ac VHT80	MCS0 ~ MCS9	10.5

15.3.4 ISED Operation Mode and Frequency Band

Table 50 shows the operation and frequency band for ISED.

Table 50: Operation Mode and Frequency Band

WLAN	STA	2.4 GHz	11b/g/n/ac	HT20	1ch - 11ch					
		5 GHz	11a	HT20	W52/53/56/58 with ch144/142/138 DFS (Device without Radar detection capability) No TPC					
			11n	HT20/40						
			11ac	VHT20/40/80						
	AP	2.4 GHz	11b/g/n/ac	11a	HT20	1ch - 11ch				
							5 GHz	11a	HT20	W52/58 with ch144/142/138 No TPC
								11n	HT20/40	
		11ac	VHT20/40/80							
BT	BR / EDR / LE (1/2 Mbps)									

15.3.5 ISED Theory of Operation

Table 51 shows the theory of operation for WLAN.

Table 51: ISED Theory of Operation for WLAN - Channel List

Frequency of Operation			Scan	Ad-hoc
2.4 GHz	11b/g/n (HT20)	2412-2462 MHz	Active	Yes
	BT	2402-2480 MHz	N/A	N/A
	BLE	2402-2480 MHz	N/A	N/A
W52	11a/n/ac ((V)HT20)	5180-5240 MHz	Active	No
	11n/ac ((V)HT40)	5190-5230 MHz	Active	No
	11ac (VHT80)	5210 MHz	Active	No
W53	11a/n/ac ((V)HT20)	5260-5320 MHz	Passive	No
	11n/ac ((V)HT40)	5270-5310 MHz	Passive	No
	11ac (VHT80)	5290 MHz	Passive	No
W56	11a/n/ac ((V)HT20)	5500-5720 MHz ³	Passive	No
	11n/ac ((V)HT40)	5510-5710 MHz ³	Passive	No
	11ac (VHT80)	5530-5690 MHz ³	Passive	No
W58	11a/n/ac ((V)HT20)	5745-5825 MHz	Active	Yes

³ The frequency band 5600 MHz-5640 MHz (11a/n/ac 20M band), 5590 MHz-5630 MHz (11n/ac 40M band) and 5610 MHz (11ac 80M band) is restricted in ISED.

	11n/ac ((V)HT40)	5755-5795 MHz	Active	Yes
	11ac (VHT80)	5775 MHz	Active	Yes



End users are not permitted to modify the software because F/W & driver are installed in device.

15.4 Europe

Table 52 and **Table 53** show the IC SISO and MIMO simultaneous transmission per antenna port power table for 2.4 GHz for WLAN. **Table 54**, **Table 55**, and **Table 56** show the IC SISO simultaneous transmission per antenna port power table for 5 GHz WLAN.

Table 57, **Table 58**, and **Table 59** show the IC MIMO simultaneous transmission per antenna port power table for 5 GHz WLAN.

Table 52: Europe Power Level 2.4 GHz WLAN Per Antenna Port (SISO/1SS)

Mode	Rate	Typical Output Power Level (dBm)	
		1 ~ 12	13
Channels		1 ~ 12	13
IEEE 802.11b	All Rates	11.5	11.5
IEEE 802.11g	All Rates	13.5	13.0
IEEE 802.11n (HT20)	MCS0 ~ MCS7	14.0	13.25
Equivalent to IEEE 802.11ac (VHT20)	MCS0 ~ MCS8	14.0	13.25

Table 53: Europe Power Level 2.4 GHz WLAN Per Antenna Port (MIMO/2SS)

Mode	Rate	Typical Output Power Level (dBm)	
		1 ~ 12	13
Channels		1 ~ 12	13
IEEE 802.11n (HT20)	MCS8 ~ MCS15	11.0	10.25
Equivalent to IEEE 802.11ac (VHT20)	MCS0 ~ MCS8	11.0	10.25

Table 54: Europe Power Level 5 GHz WLAN Per Antenna Port (SISO/1SS) (W52-53)

Mode	Rate	Typical Output Power Level (dBm)	
		36 ~ 64	38 ~ 62
Channels		36 ~ 64	38 ~ 62
11a	6 ~ 54 Mbps	13.0	
11n/ac HT20	MCS0 ~ MCS7	13.0	
11ac VHT20	MCS8	12.0	
Channels		38 ~ 62	
11n/ac HT40	MCS0 ~ MCS5	14.0	
	MCS6	13.0	
	MCS7	12.0	
11ac VHT40	MCS8	11.0	
	MCS9	10.0	

Mode	Rate	Typical Output Power Level (dBm)
Channels		42 ~ 58
11ac VHT80	MCS0 ~ MCS5	14.0
	MCS6	13.0
	MCS7	12.0
	MCS8	11.0
	MCS9	10.0

Table 55: Europe Power Level 5 GHz WLAN Per Antenna Port (SISO/1SS) (W56)

Mode	Rate	Typical Output Power Level (dBm)			
Channels		100 ~ 128	132 ~ 136	140	144
11a	6 ~ 54 Mbps	13.0	13.0	13.0	13.0
11n/ac HT20	MCS0 ~ MCS7	13.0	13.0	13.0	13.0
11ac VHT20	MCS8	12.0	12.0	12.0	12.0
Channels		102 ~ 126	134	142	
11n/ac HT40	MCS0 ~ MCS5	14.0	14.0		
	MCS6	13.0	13.0		
	MCS7	12.0	12.0		
11ac VHT40	MCS8	11.0	11.0		
	MCS9	10.0	10.0		
Channels		106 ~ 122		138	
11ac VHT80	MCS0 ~ MCS5	14.0			
	MCS6	13.0			
	MCS7	12.0			
	MCS8	11.0			
	MCS9	10.0			

Table 56: Europe Power Level 5 GHz WLAN Per Antenna Port (SISO/1SS) (W58)

Mode	Rate	Typical Output Power Level (dBm)	
Channels		149 ~ 161	165
11a	6 ~ 54 Mbps	6.5	6.5
11n/ac HT20	MCS0 ~ MCS7	6.5	6.5
11ac VHT20	MCS8	6.5	6.5
Channels		151 ~ 159	
11n/ac HT40	MCS0 ~ MCS7	6.5	
11ac VHT40	MCS8	6.5	
Channels		155	
11ac VHT80	MCS0 ~ MCS9	6.5	

Table 57: Europe Power Level 5 GHz WLAN Per Antenna Port (MIMO/2SS) (W52-53)

Mode	Rate	Typical Output Power Level (dBm)
Channels		36 ~ 64
11n HT20	MCS0 ~ MCS7	13.0
11ac VHT20	MCS8	12.0
Channels		38 ~ 62
11n HT40	MCS8 ~ MCS14	12.5
	MCS15	12.0
11ac VHT40	MCS0 ~ MCS6	12.5
	MCS7	12.0
	MCS8	11.0
	MCS9	10.0
Channels		42 ~ 58
11ac VHT80	MCS0 ~ MCS7	12.0
	MCS8	11.0
	MCS9	10.0

Table 58: Europe Power Level 5 GHz WLAN Per Antenna Port (MIMO/2SS) (W56)

Mode	Rate	Typical Output Power Level (dBm)			
Channels		100 ~ 128	132 ~ 136	140	144
11n/ac HT20	MCS8 ~ MCS15	10.0	10.0	10.0	10.0
11ac VHT20	MCS0 ~ MCS8	10.0	10.0	10.0	10.0
Channels		102 ~ 126	134	142	
11n/ac HT40	MCS8 ~ MCS14	12.5	12.5		
	MCS15	12.0	12.0		
11ac VHT40	MCS0 ~ MCS6	12.5	12.5		
	MCS7	12.0	12.0		
	MCS8	11.0	11.0		
	MCS9	10.0	10.0		
Channels		106 ~ 122	138		
11ac VHT80	MCS0 ~ MCS7	12.0			
	MCS8	11.0			
	MCS9	10.0			

Table 59: Europe Power Level 5 GHz WLAN Per Antenna Port (MIMO/2SS) (W58)

Mode	Rate	Typical Output Power Level (dBm)	
Channels		149 ~ 161	165
11n/ac HT20	MCS8 ~ MCS15	3.5	3.5
11ac VHT20	MCS0 ~ MCS8	3.5	3.5
Channels		151 ~ 159	
11n/ac HT40	MCS8 ~ MCS15	3.5	
11ac VHT40	MCS0 ~ MCS8	3.5	

Mode	Rate	Typical Output Power Level (dBm)
Channels:		155
11ac VHT80	MCS0 ~ MCS9	2.5

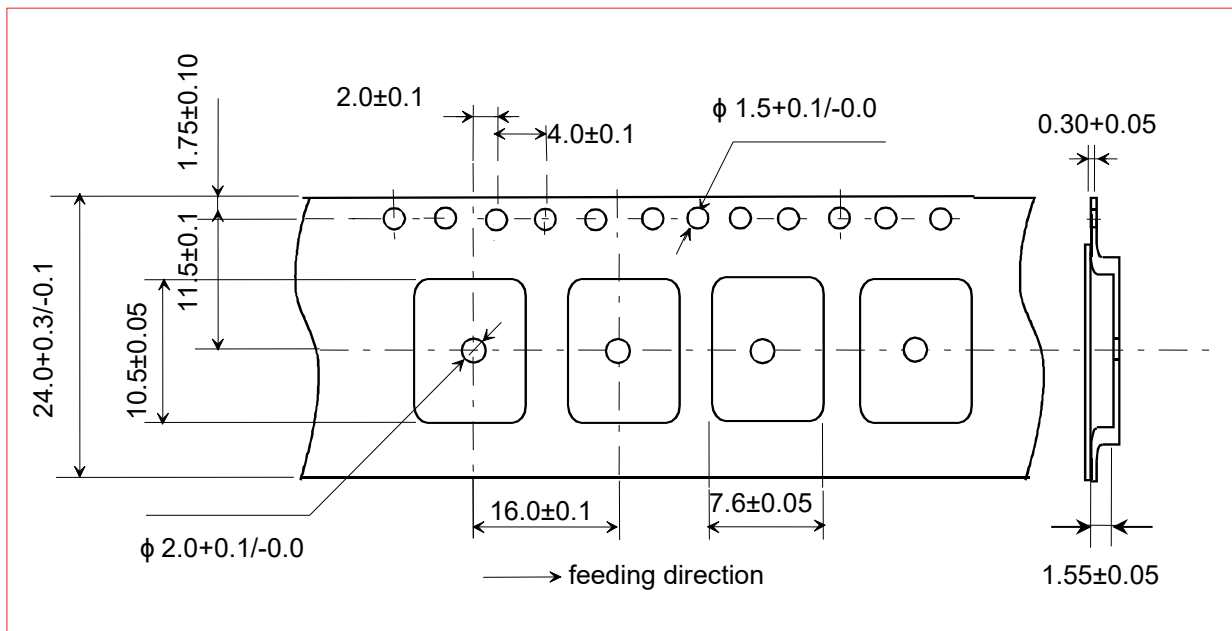
16 Tape and Reel Packing

This section provides the general specifications for tape and reel packing.

16.1 Dimensions of Tape (Plastic Tape)

Figure 21 is a graphical representation of the tape dimension (plastic tape).

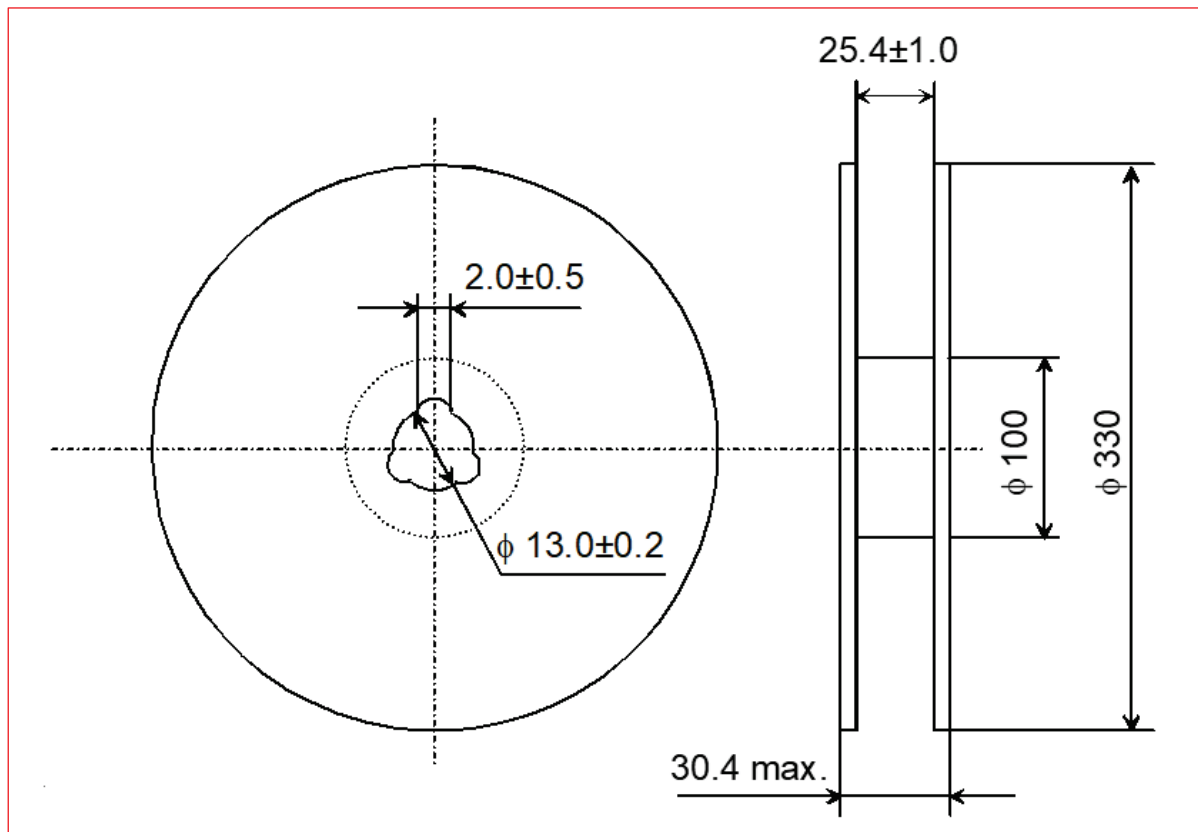
Figure 21: Dimensions of Tape (Unit: mm)



16.2 Dimension of Reel

Figure 22 shows the reel dimensions.

Figure 22: Dimensions of Reel (Unit: mm)



16.3 Taping Diagrams

Figure 23 shows the tapings diagrams.

Figure 23: Taping Diagrams

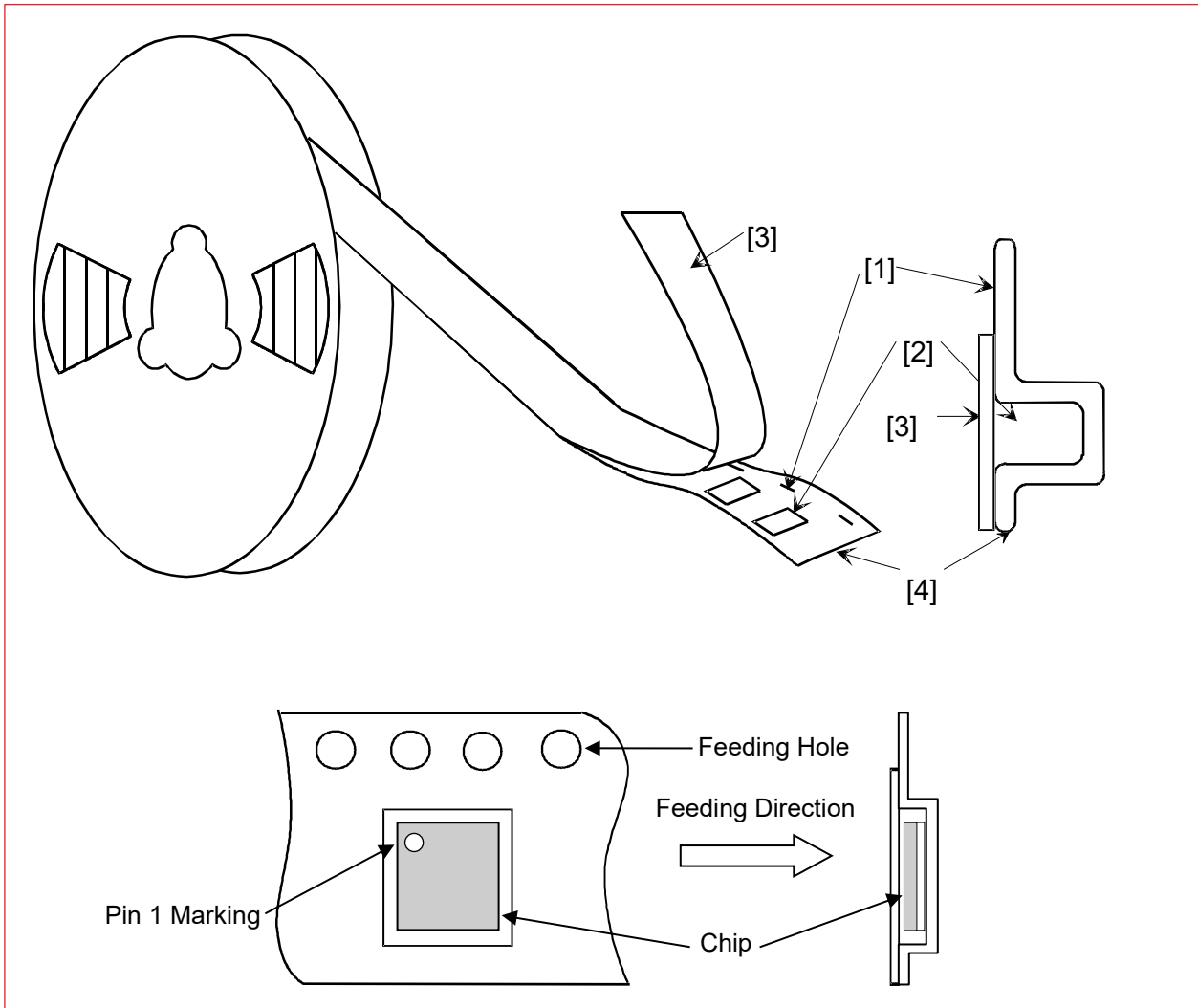





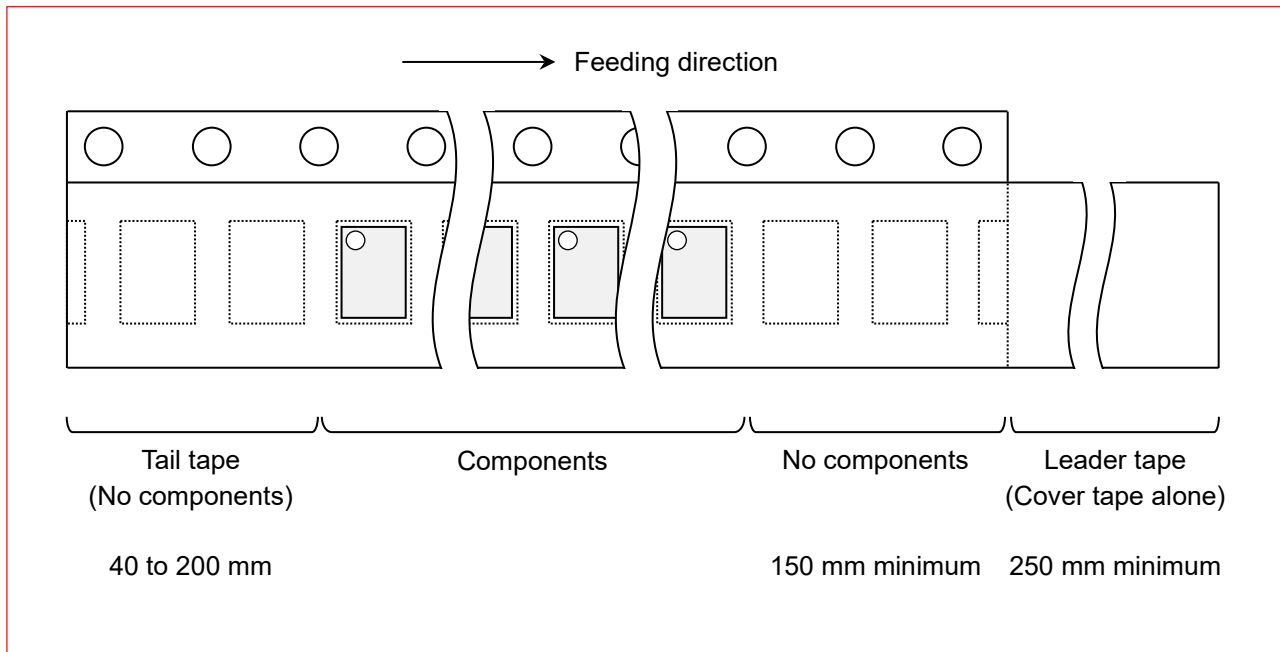
Table 60: Taping Specifications

Mark	Descriptions
[1] Feeding Hole	As specified in Dimensions of Tape 
[2] Hole for chip	As specified in Dimensions of Tape 
[3] Cover tape	62 μm in thickness
[4] Base tape	As specified in Dimensions of Tape 

16.4 Leader and Tail Tape

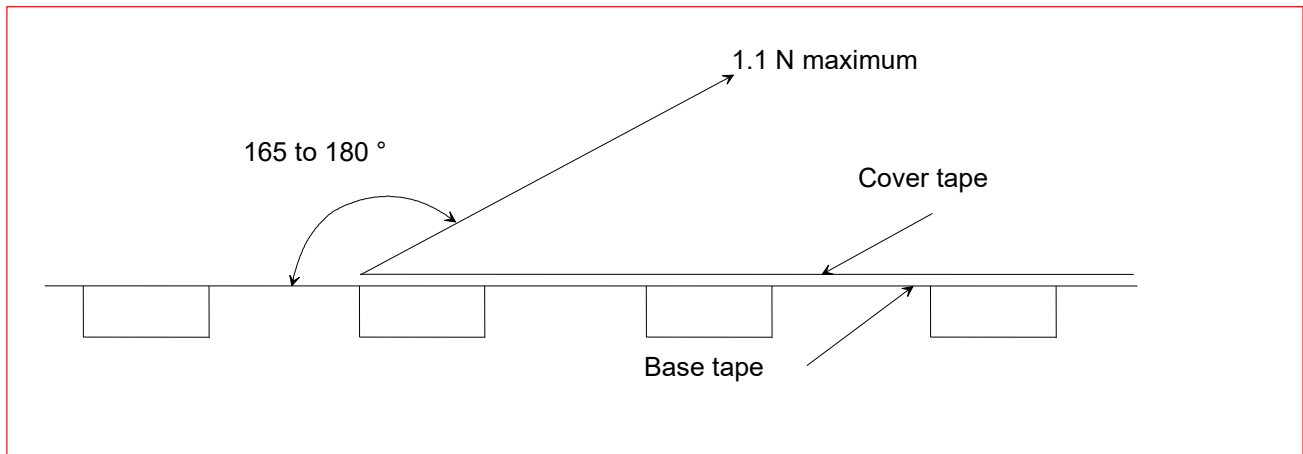
The leader and tail tape are shown in **Figure 24**.

Figure 24: Leader and Tail Tape



- The tape for chips is wound clockwise, the feeding holes to the right side as the tape is pulled toward the user.
- The cover tape and base tape are not adhered at no components area for 250 mm minimum.
- Tear off strength against pulling of cover tape: 5 N minimum.
- Packaging unit: 1000 pcs. / Reel
- Tape material:
 - Base tape: Plastic
 - Reel: Plastic
 - Cover tape, cavity tape and reel are made the anti-static processing.
- Peeling off force: 1.1 N maximum in the direction of peeling as shown in **Figure 25**.

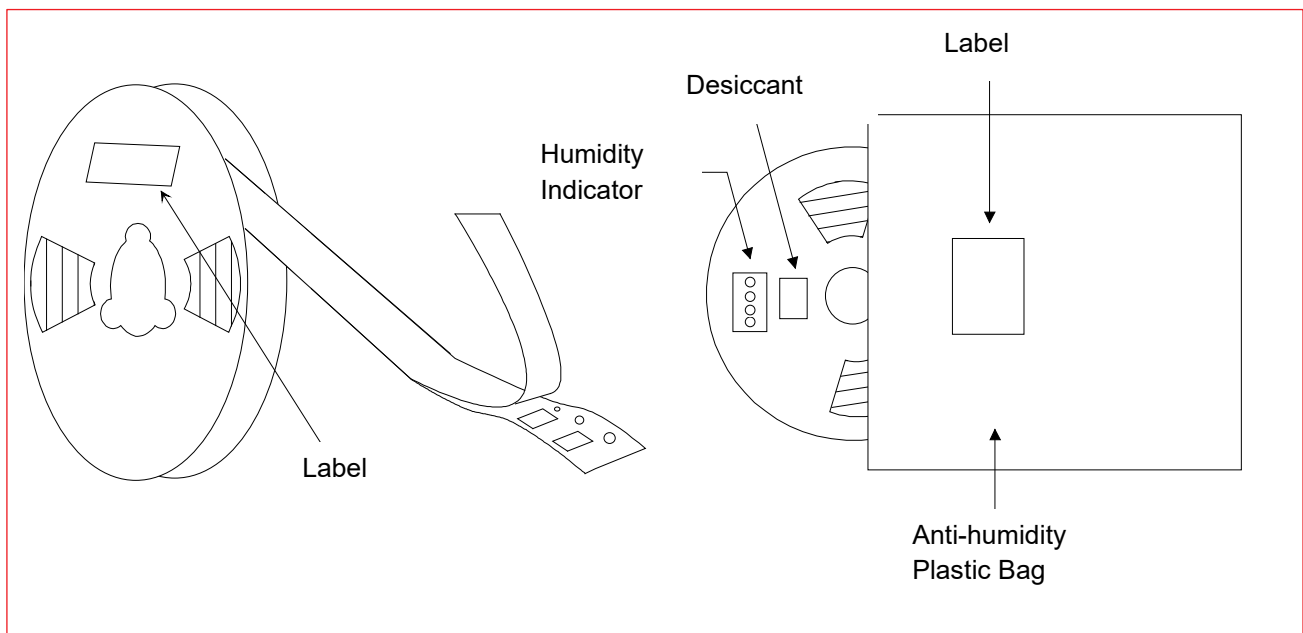
Figure 25: Peeling Off Force



16.5 Packaging (Humidity Proof Packing)

Figure 26 shows the humidity proof packaging.

Figure 26: Humidity Proof Packaging



Tape and reel must be sealed with the anti-humidity plastic bag. The bag contains the desiccant and the humidity indicator.

17 Notice

17.1 Storage Conditions

- Please use this product within 6 months after receipt.
- The product shall be stored without opening the packing under the ambient temperature from 5 to 35 °C and humidity from 20 ~ 70 %RH (Packing materials may be deformed at the temperature over 40 °C).
- The product left more than 6 months after reception; it needs to be confirmed the solderability before used.
- The product shall be stored in noncorrosive gas (Cl₂, NH₃, SO₂, NO_x, etc.).
- Any excess mechanical shock including, but not limited to, sticking the packing materials by sharp object and dropping the product, shall not be applied in order not to damage the packing materials.
- This product is applicable to MSL3 (Based on JEDEC Standard J-STD-020)
 - After the packing is opened, the product shall be stored at ≤ 30 °C / ≤ 60 %RH and the product shall be used within 168 hours.
 - When the color of the indicator in the packing changed, the product shall be baked before soldering.
- Baking condition: 125 +5/-0 °C, 24 hours, 1 time
- The products shall be baked on the heat-resistant tray because the materials (Base Tape, Reel Tape and Cover Tape) are not heat-resistant.

17.2 Handling Conditions

- Be careful in handling or transporting products because excessive stress or mechanical shock may break products.
- Handle with care if products may have cracks or damages on their terminals, the characteristics of products may change. Do not touch products with bare hands that may result in poor solderability and damage by static electrical charge.

17.3 Standard PCB Design (Land Pattern and Dimensions):

- All the ground terminals should be connected to the ground patterns. Furthermore, the ground pattern should be provided between IN and OUT terminals. Please refer to the specifications for the standard land dimensions.
- The recommended land pattern and dimensions is as Murata's standard. The characteristics of products may vary depending on the pattern drawing method, grounding method, land dimensions, land forming method of the NC terminals and the PCB material and thickness. Therefore, be sure to verify the characteristics in the actual set. When using non-standard lands, contact Murata beforehand.

17.4 Notice for Chip Placer

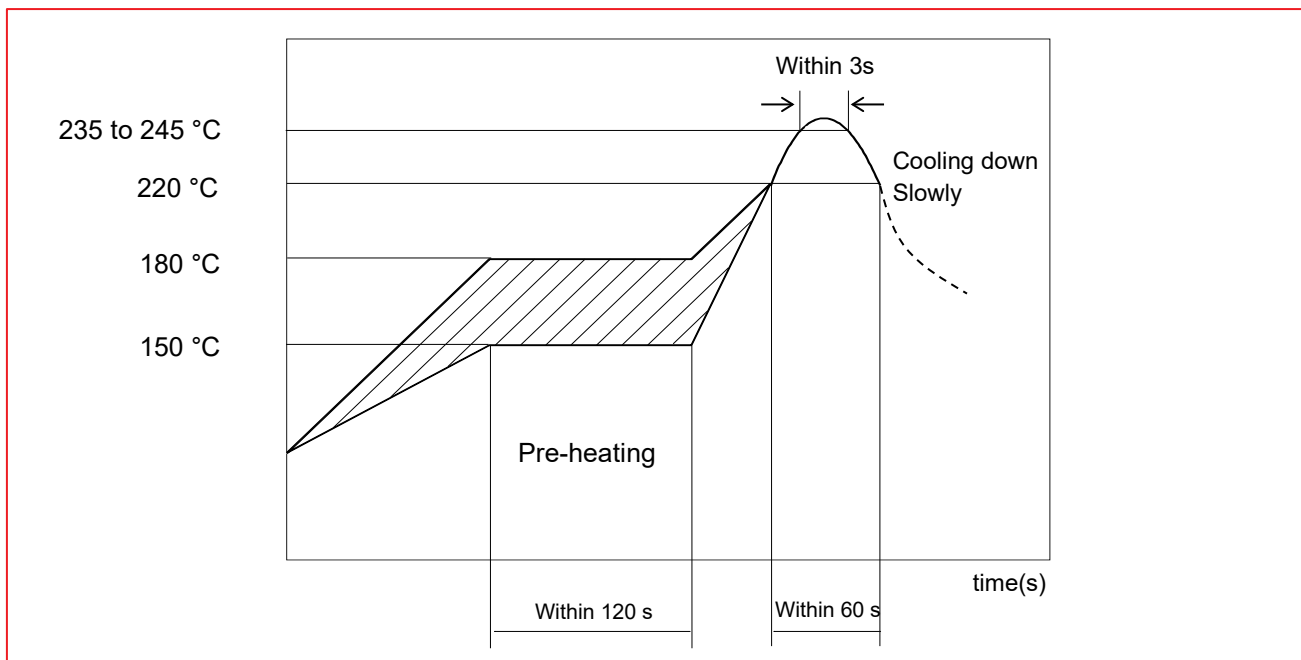
When placing products on the PCB, products may be stressed and broken by uneven forces from a worn-out chucking locating claw or a suction nozzle. To prevent products from damages, be sure to follow the specifications for the maintenance of the chip placer being used. For the positioning of products on the PCB, be aware that mechanical chucking may damage products.

17.5 Soldering Conditions

The recommendation conditions of soldering are shown in **Figure 27**.

Soldering must be carried out by the above-mentioned conditions to prevent products from damage. Set up the highest temperature of reflow within 260 °C. Contact Murata before use if concerning other soldering conditions.

Figure 27: Reflow Soldering Standard Conditions (Example)



Please use the reflow within 2 times. Use rosin type flux or weakly active flux with a chlorine content of 0.2 wt. % or less.

17.6 Cleaning

This product is moisture sensitive therefore, cleaning is not permitted. If any cleaning process is done the customer is responsible for any issues or failures caused by the cleaning process.

17.7 Operational Environment Conditions

Products are designed to work for electronic products under normal environmental conditions (ambient temperature, humidity, and pressure). Therefore, products have no problems to be used under the similar conditions to the above-mentioned. However, if products are used under the following circumstances, it may damage products and leakage of electricity and abnormal temperature may occur.

- In an atmosphere containing corrosive gas (CL₂, NH₃, SO_x, NO_x, etc.).
- In an atmosphere containing combustible and volatile gases.
- Dusty place.
- Direct sunlight place.
- Water splashing place.
- Humid place where water condenses.
- Freezing place.



If there are possibilities for products to be used under the preceding clause, make sure to consult with Murata before actual use.



Do not apply static electricity or excessive voltage while assembling and measuring, as it might be a cause of degradation or destruction to apply static electricity to products.

17.8 Input Power Capacity

Products shall be used in the input power capacity as specified in this specification.

Inform Murata beforehand, in case that the components are used beyond such input power capacity range.

18 Preconditions to Use Our Products



PLEASE READ THIS NOTICE BEFORE USING OUR PRODUCTS.

Please make sure that your product has been evaluated and confirmed from the aspect of the fitness for the specifications of our product when our product is mounted to your product.

All the items and parameters in this product specification/datasheet/catalog have been prescribed on the premise that our product is used for the purpose, under the condition and in the environment specified in this specification. You are requested not to use our product deviating from the condition and the environment specified in this specification.

Please note that the only warranty that we provide regarding the products is its conformance to the specifications provided herein. Accordingly, we shall not be responsible for any defects in products or equipment incorporating such products, which are caused under the conditions other than those specified in this specification.

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- Aerospace equipment.
- Undersea equipment.
- Power plant control equipment.
- Medical equipment.
- Traffic signal equipment.

- Burning / explosion control equipment.
- Disaster prevention / crime prevention equipment.
- Transportation equipment (vehicles, trains, ships, elevator, etc.).
- Application of similar complexity and/ or reliability requirements to the applications listed in the above.

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Revision History

Revision Code	Date	Changed Item	Comment
	2019.04.18	First Issue	
A	2020.06.05	9. MODULE PIN DESCRIPTIONS	<ul style="list-style-type: none"> Changed then name of pin 57 from VDDIO_SD to VDDIO. Changed the name of pin 31 from RF_SW_CTRL13 to RF_SW_CTRL11.
B	2020.07.17	8. DIMENSIONS	Added Solder bump and defined T1 dimension
C	2020.10.29	KEY FEATURE 4. SAMPLE ORDERING INFORMATION 6. OPERATING CONDITION 11. I/O States 14. ELECTRICAL CHARACTERISTICS	<ul style="list-style-type: none"> Added Weight information. Changed sample and EVB P/N. Added operating temperature spec. Corrected Typ. VBAT from 3.6V to 3.3V Added I/O State Table Added Output power spec.
D	2020.11.11	8. DIMENSIONS, MARKING AND TERMINAL CONFIGURATIONS 10. REFERENCE PERIPHERAL CIRCUIT	<ul style="list-style-type: none"> Added Marking information. Added Reference circuit.
E	2020.12.14	1. SCOPE 14.9. DC/RF Characteristics for Bluetooth	<ul style="list-style-type: none"> Modified Bluetooth version. Corrected Minimum output power.
F	2021.01.28	8. DIMENSIONS, MARKING AND TERMINAL CONFIGURATIONS 14. ELECTORICAL CHARACTERISTICS	<ul style="list-style-type: none"> Added pin 1 mark information on Bottom view. Added current consumption information.
G	2021.02.01	14.7. DC/RF Characteristics for IEEE802.11ac(HT 40MHz) - 5GHz 14.8. DC/RF Characteristics for IEEE802.11ac(HT 80MHz) - 5GHz	Optimized the max value of current consumption for VHT40/80 of 5GHz mode.
H	2021.03.02	Appendix.	Added User's guide of certification.
I	2021.04.01	10. REFERENCE PERIPHERAL CIRCUIT	Applied the regulatory certification condition.
J	2021.11.29	6. OPERATING CONDITION	Added Specification Temperature
K	2022.06.30	Cover Page 2. KEY FEATURE	Changed IC vendor name to Infineon
L	2023.09.13	2. Key Features 4. Sample Ordering Information 10. Reference Peripheral Circuit 14. Electrical Characteristics Appendix	<ul style="list-style-type: none"> Updated information Added Embedded Artists' M.2 module information. Renamed section. Moved to before Block Diagram. Moved section to HW app note. Renamed section Moved Appendix information into Section 15. Added transmit power tables. Added Europe section. Moved antenna sections to HW app note.
			Updated to new format



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